EUV Lithography : Progress in LPP Source Power Scaling and Availability

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Outline

- Background and History
- EUV Imaging
- EUV Principles of Generation
- EUV Source: Architecture
- EUV Sources in the Field
- Performance Outlook
- Summary

Background and History

Why EUV? - Resolution in Optical Lithography

Critical Dimension

$$CD = k_1 \cdot \frac{\lambda}{NA}$$

λ

KrF-Laser : 248nm
ArF-Laser: 193 nm
ArF-Laser (i): 193 nm
EUV sources: 13.5 nm

k_1

k_1 is process parameter
traditionally: >0.75
typically: 0.3 – 0.4
theoretical limit: 0.25

NA = n sinα

theoretical limit (air):
NA=1
practical limit:
NA=0.9
theoretical limit (immersion):
NA ≈ n (~1.7)

EUV development has progressed over 30 years

from NGL to HVM insertion

1st lithography (LLNL, Bell Labs, Japan)

ASML starts EUVL research program

ASML ships 2 alpha demo tools: IMEC (Belgium) and CNSE (USA)

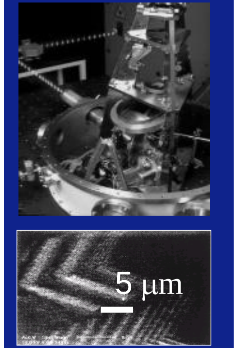
ASML ships 1st pre-production NA 0.25 system NXE:3100

ASML ships 1st NA 0.33 system NXE:3300B

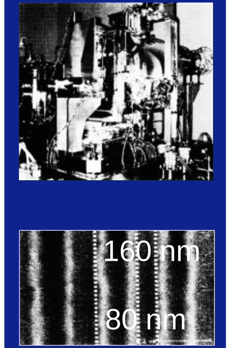
ASML ships 1st HVM NA0.33 system NXE:3400B

’85 ’86 ’87 ’88 ’89 ’90 ’91 ’92 ’93 ’94 ’95 ’96 ’97 ’98 ’99 ’00 ’01 ’02 ’03 ’04 ’05 ’06 ’07 ’08 ’09 ’10 ’11 ’12 ‘13 ’14 ’15 ’16 ’17 ’18

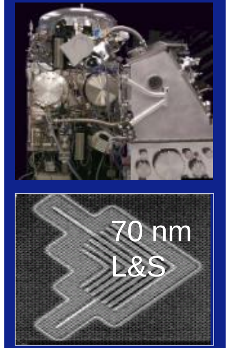
NL



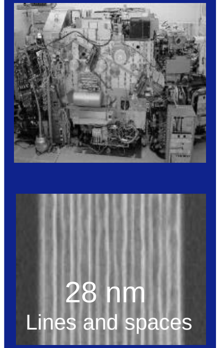
Japan



USA



NL



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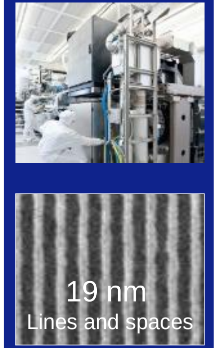
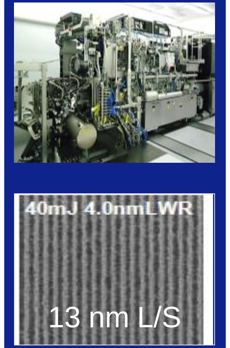
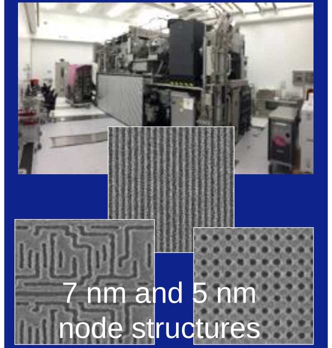


NL

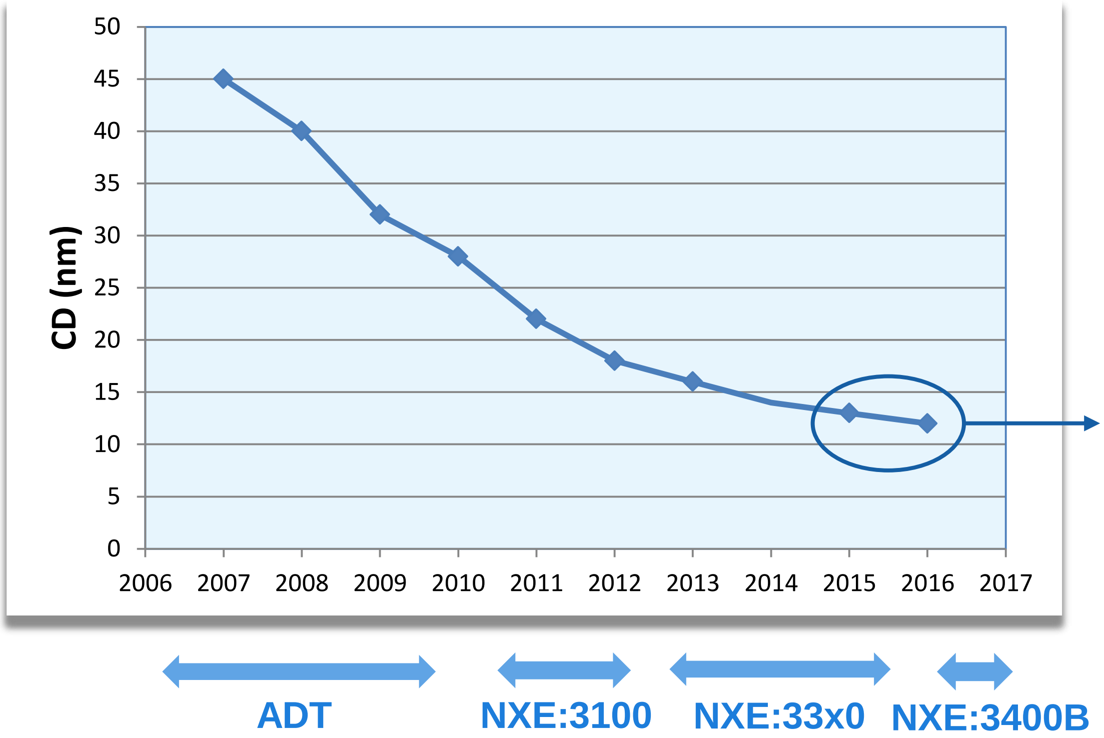


NL



EUV resist: 4x resolution improvement in ten years

12nm half pitch resolved with non-CAR resist on 0.33 NA EUV



inpria
Non-CAR resist

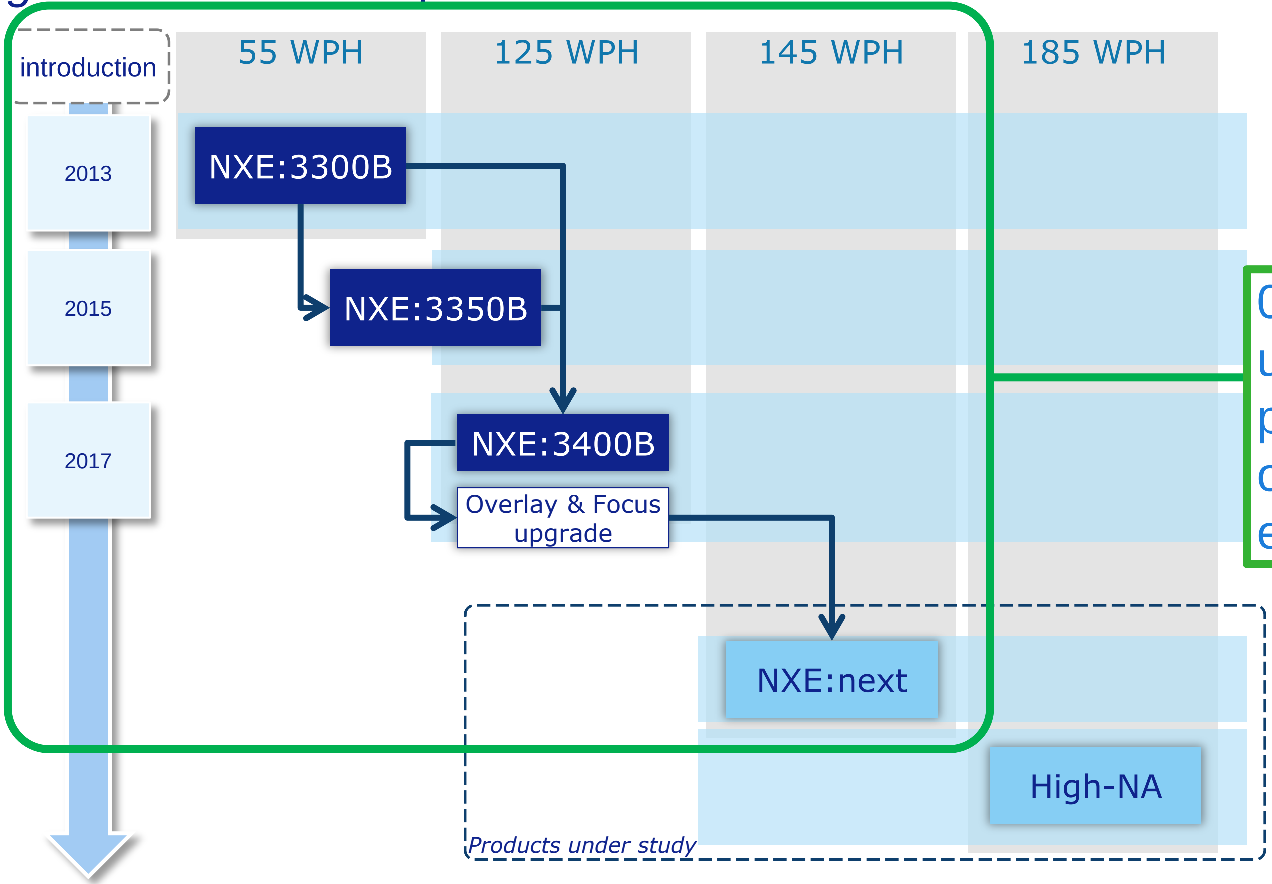
Half Pitch: 12nm

ADT, NXE:3100, NXE:33x0, NXE:3400B as measured by ASML/ IMEC,

Exposure Latitude > 10% and / or Line Width Roughness < 20%, Dose ≤ 35mJ/cm2

EUV roadmap

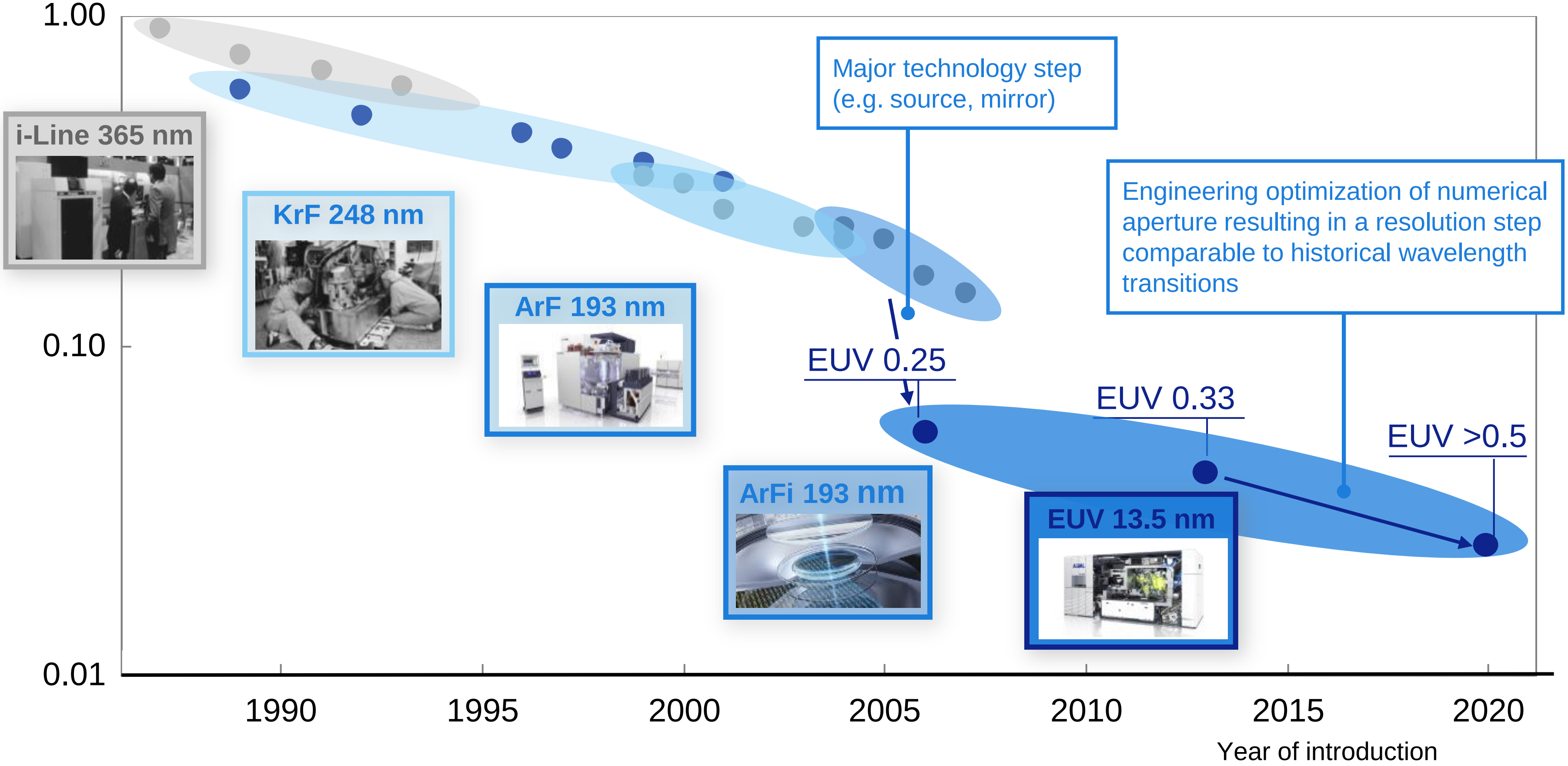
Supporting customer roadmaps well into the next decade



0.33 NA family: upgrades possible to optimize capital efficiency

High-NA EUV targets ≤8nm resolution

Relative improvement:5X over ArFi, 40% over 0.33 NA EUV



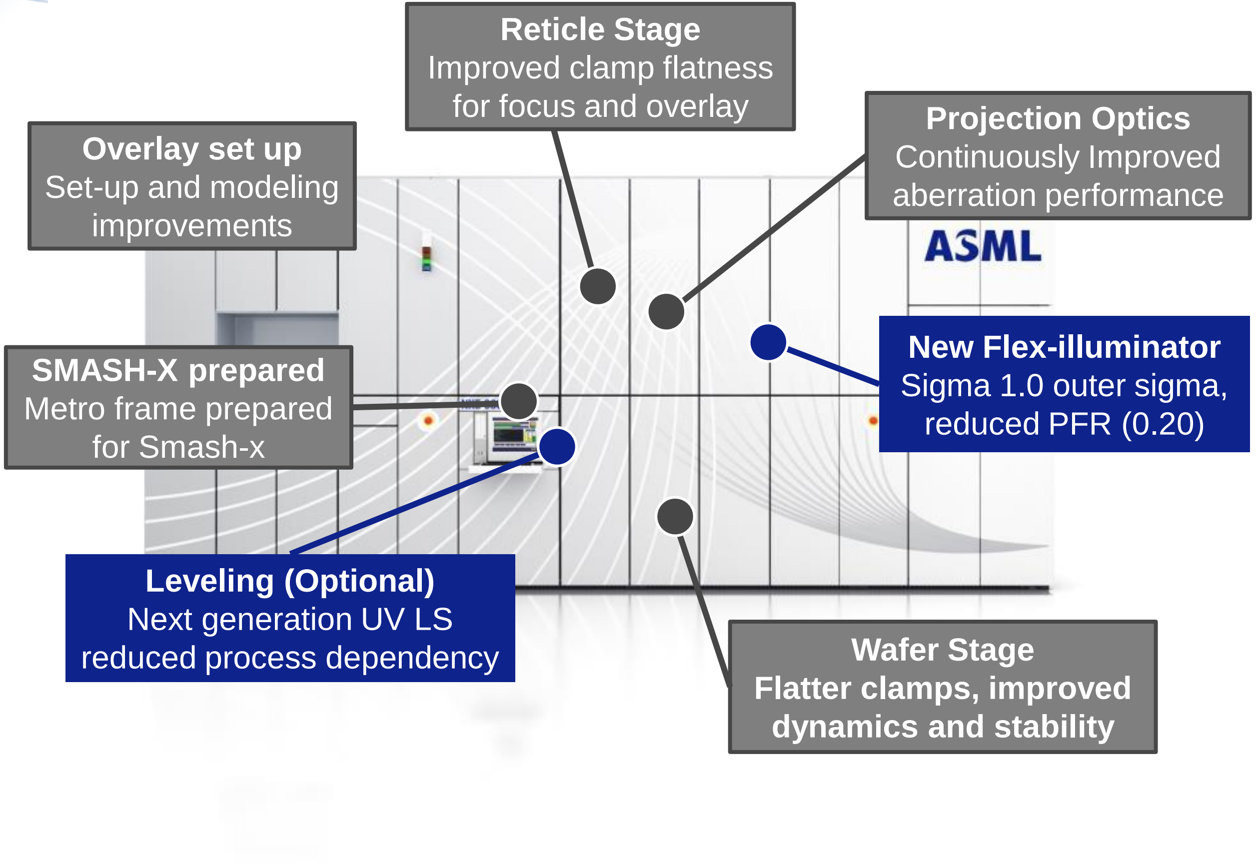
Major technology step (e.g. source, mirror)

Engineering optimization of numerical aperture resulting in a resolution step comparable to historical wavelength transitions

EUV Imaging – NXE:3400B

NXE:3400B: 13 nm resolution at full productivity

Supporting 5 nm logic, <15nm DRAM requirements



Reticle Stage
Improved clamp flatness for focus and overlay

Overlay set up
Set-up and modeling improvements

Projection Optics
Continuously Improved aberration performance

New Flex-illuminator
Sigma 1.0 outer sigma, reduced PFR (0.20)

SMASH-X prepared
Metro frame prepared for Smash-x

Leveling (Optional)
Next generation UV LS reduced process dependency

Wafer Stage
Flatter clamps, improved dynamics and stability

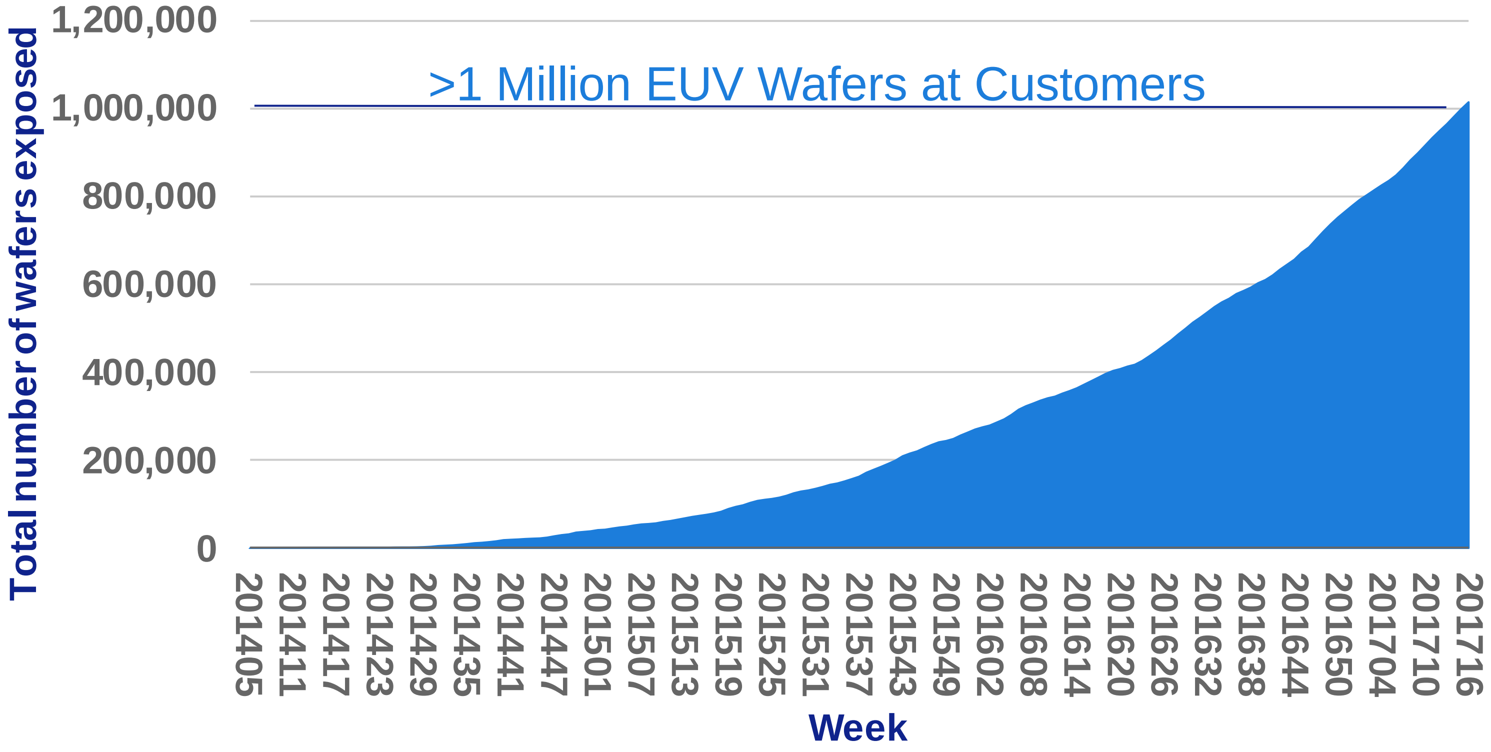
Resolution	13 nm
Full wafer CDU	≤ 1.1 nm
DCO	≤ 1.4 nm
MMO	≤ 2.0 nm
Focus control	≤ 60 nm
Productivity	≥ 125 WPH

- ▬ Overlay
- ▬ Imaging/Focus
- 🟩 Productivity

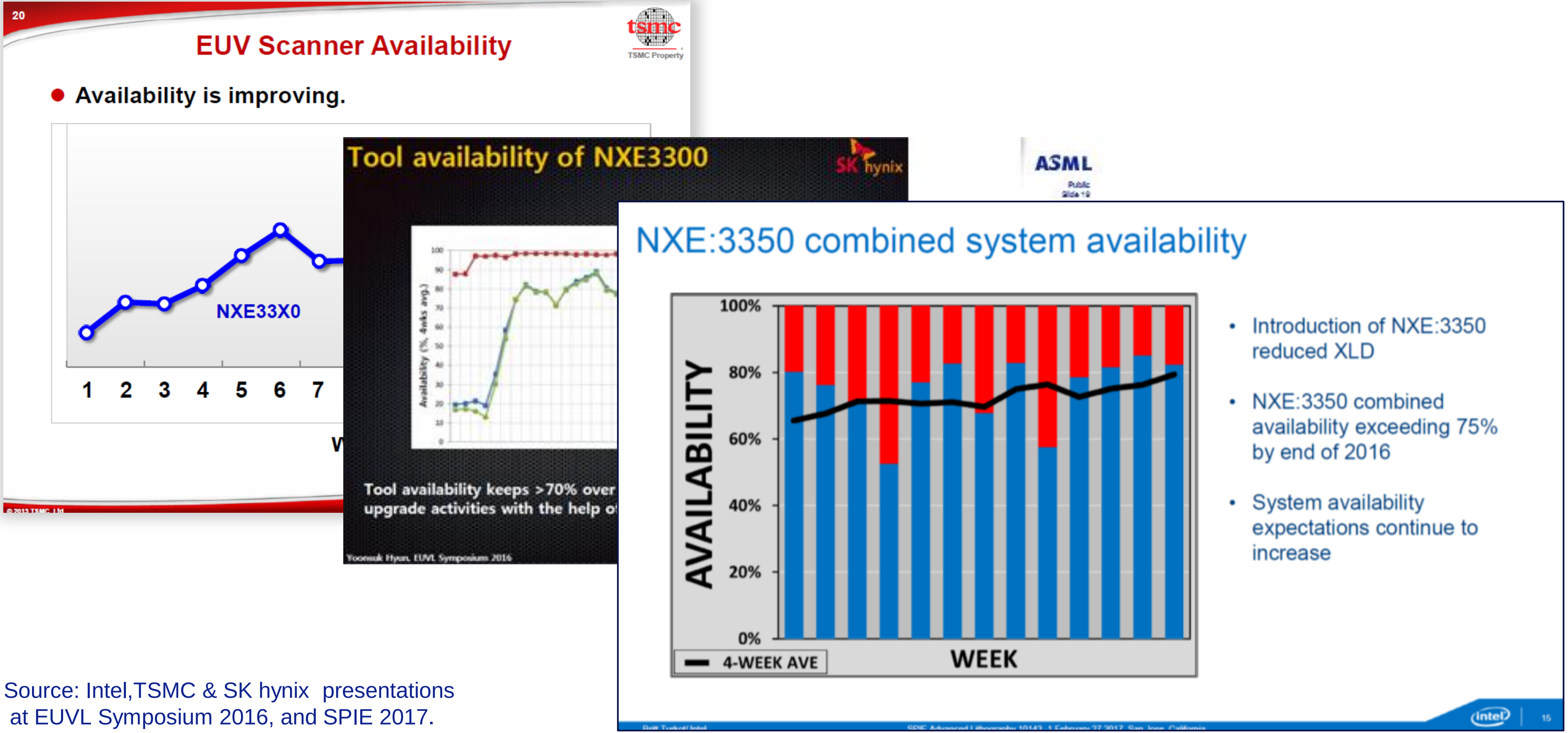
>1M wafers exposed on NXE:33x0B at customer sites

Currently 14 systems running in the field. First system was shipped Q1 2013

Public



Significant progress in system availability is recognized by our customers



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EUV Scanner Availability

TSMC Property

- Availability is improving.

Tool availability of NXE3300

Tool availability keeps >70% over
upgrade activities with the help o

Yoonsuk Hyun, EUVL Symposium 2016

NXE:3350 combined system availability

- Introduction of NXE:3350 reduced XLD
- NXE:3350 combined availability exceeding 75% by end of 2016
- System availability expectations continue to increase

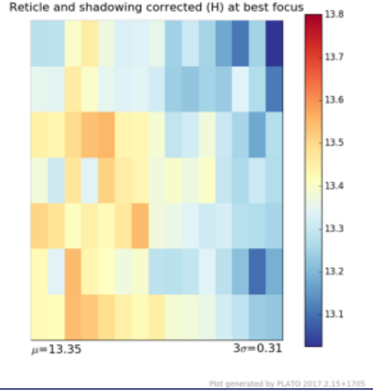
Source: Intel,TSMC & SK hynix presentations
at EUVL Symposium 2016, and SPIE 2017.

13nm LS and 16nm IS: full-wafer CDU 0.3 nm

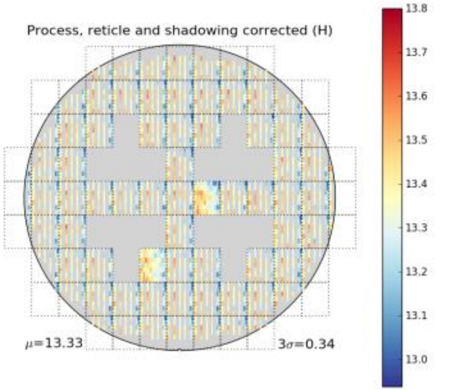
meets 5 nm logic requirements, with excellent process windows

13 nm LS
leafshape dipole

Reticle and shadowing corrected (H) at best focus



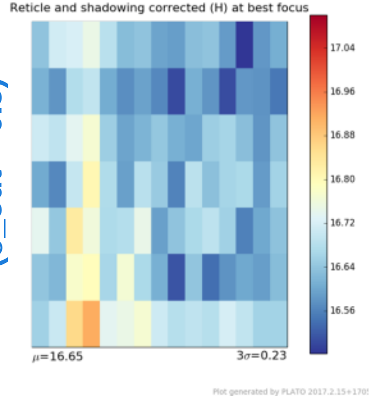
Process, reticle and shadowing corrected (H)



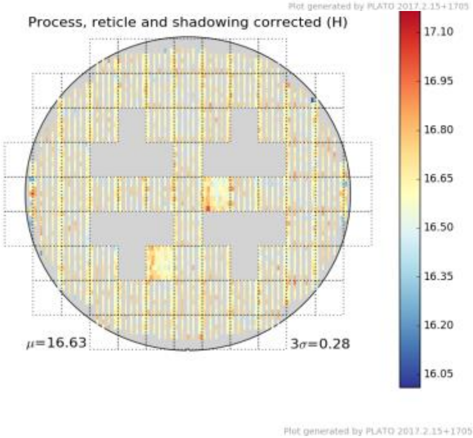
	non-CAR resist
	
Dose to size	34mJ
EL	20.7%
DoF	160nm
LWR	3.8nm

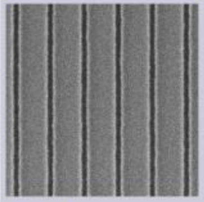
16 nm IS
small-conventional
(σ_out = 0.5)

Reticle and shadowing corrected (H) at best focus

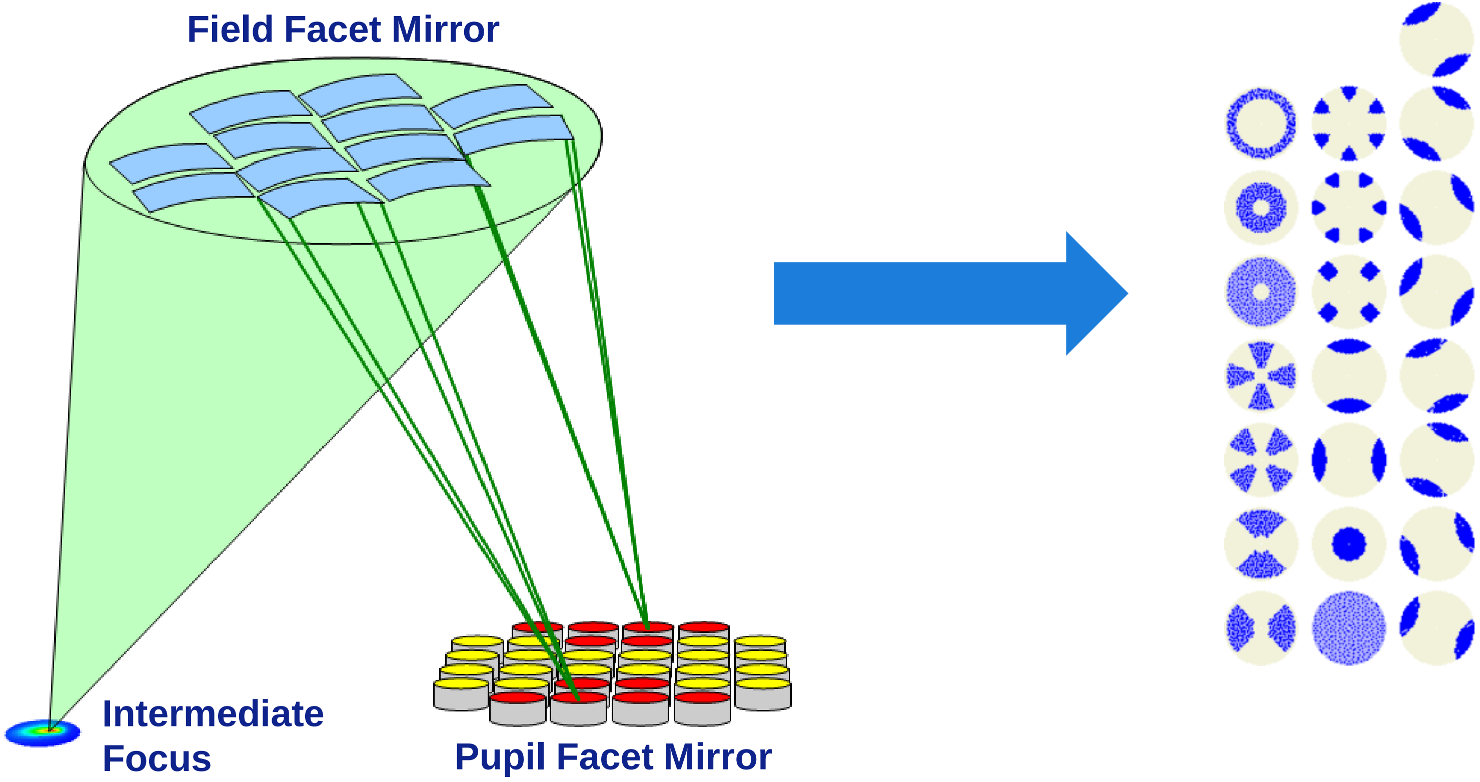


Process, reticle and shadowing corrected (H)



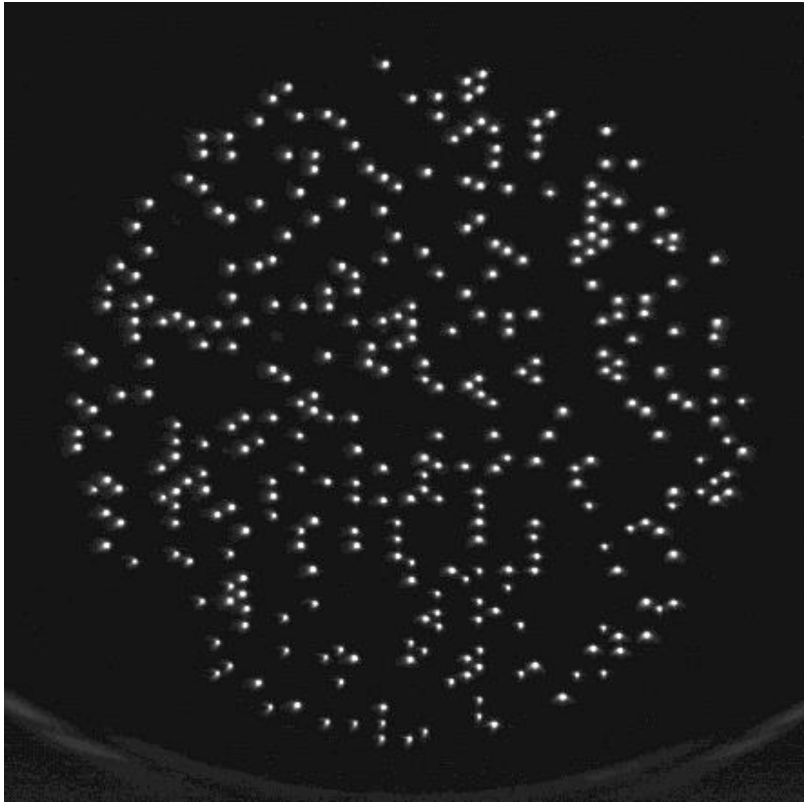
	CAR resist
	
Dose to size	58mJ
EL	18.7%
DoF	140nm
LWR	3.2nm

NXE:3400B illuminator: increased pupil flexibility at full throughput



New flex illuminator on NXE:3400B

13nm resolution without light loss at 20% pupil fill ratio

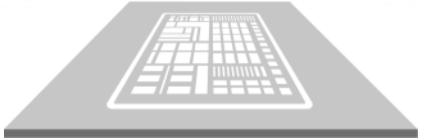


First illuminators qualified and currently being integrated in a system

The animation shows the 22 standard illumination settings. They are measured in the illuminator work center, using visible light and a camera on top of the illuminator

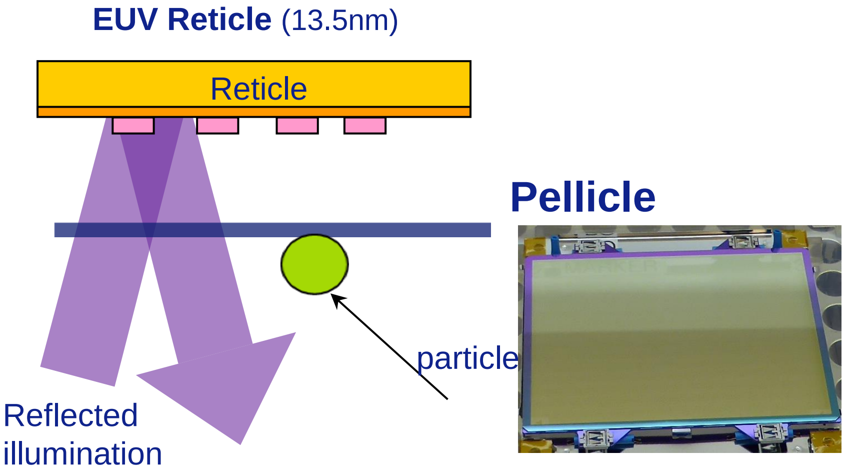
Two-fold approach to eliminate reticle front-side defects

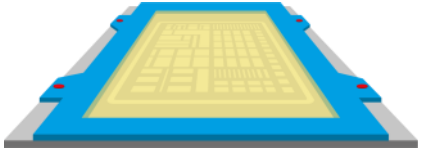
1. Clean scanner



Without Pellicle

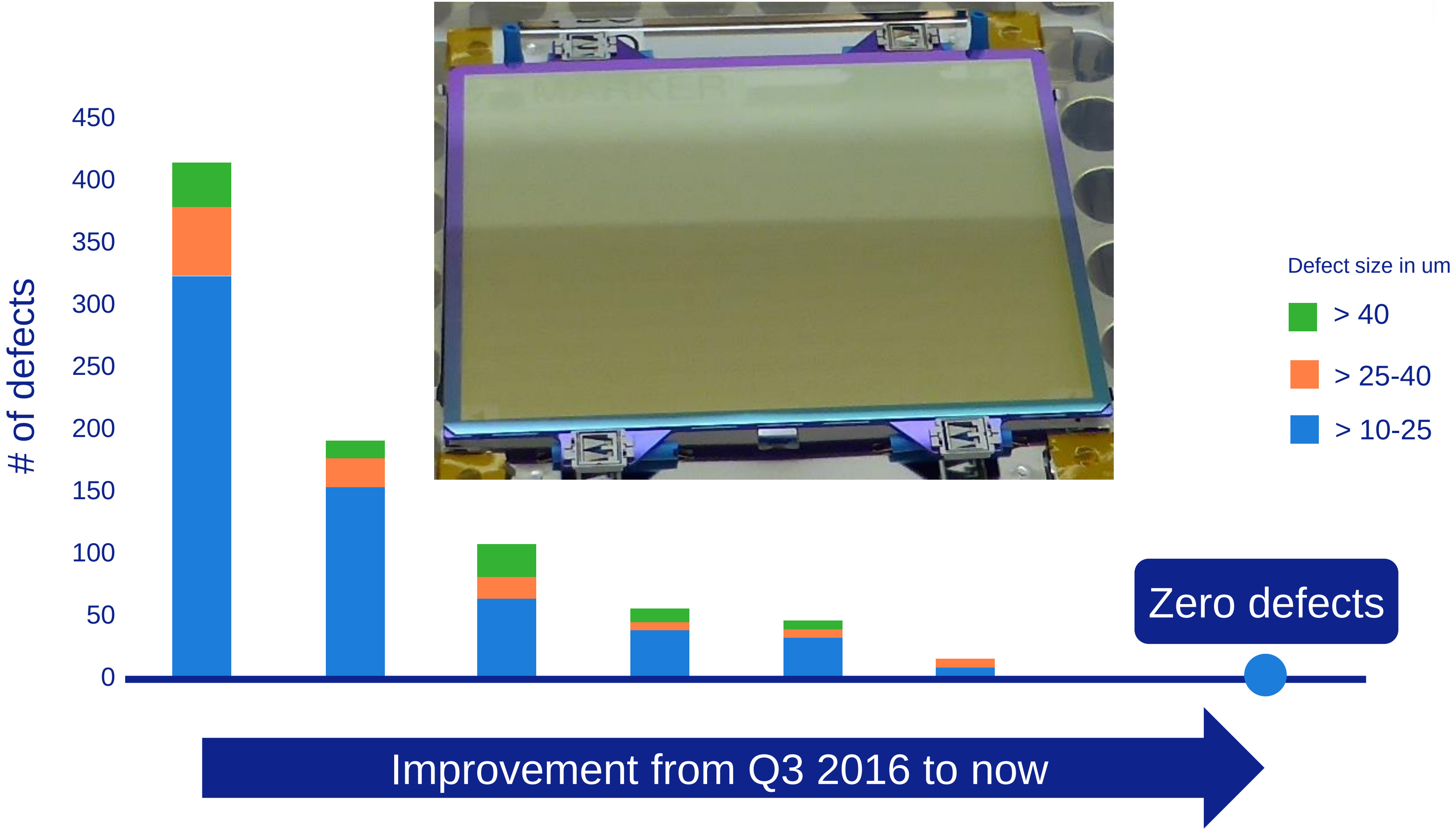
2. EUV pellicle





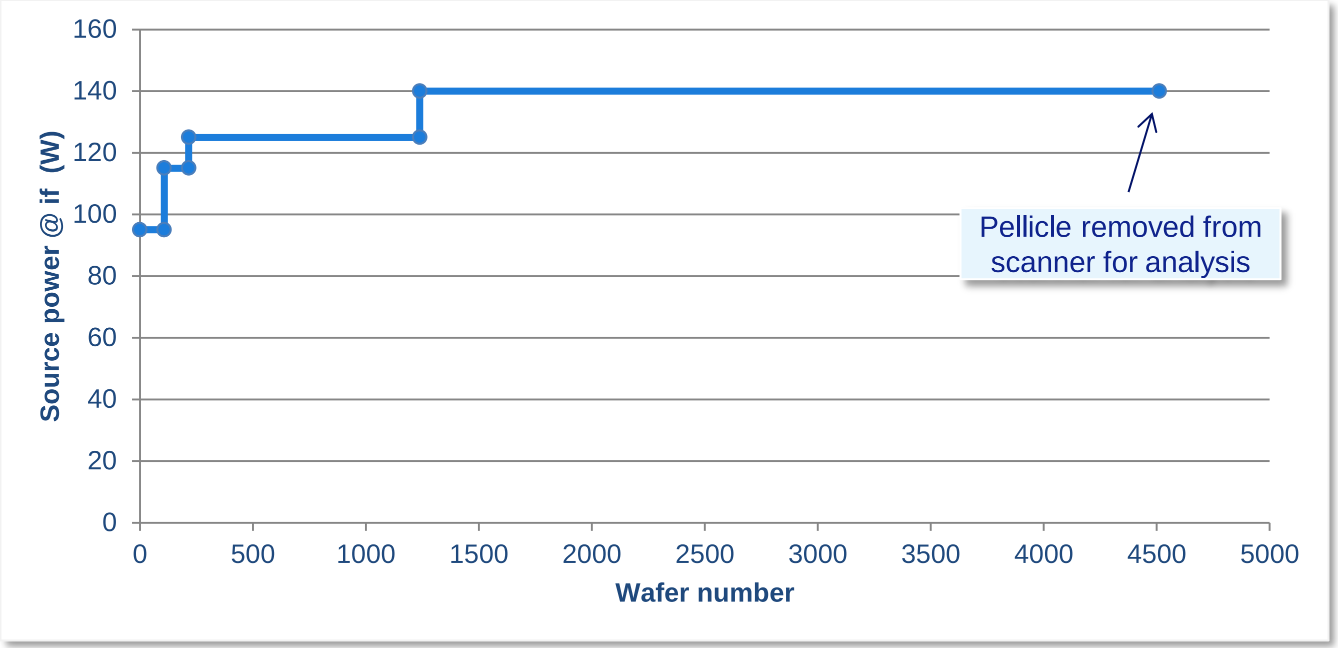
With Pellicle

Pellicle film produced without defects that print



ASML pellicle confirmed for use in NXE:3400B to at least 140W

Y-nozzle cooling can extend pellicle to >205W

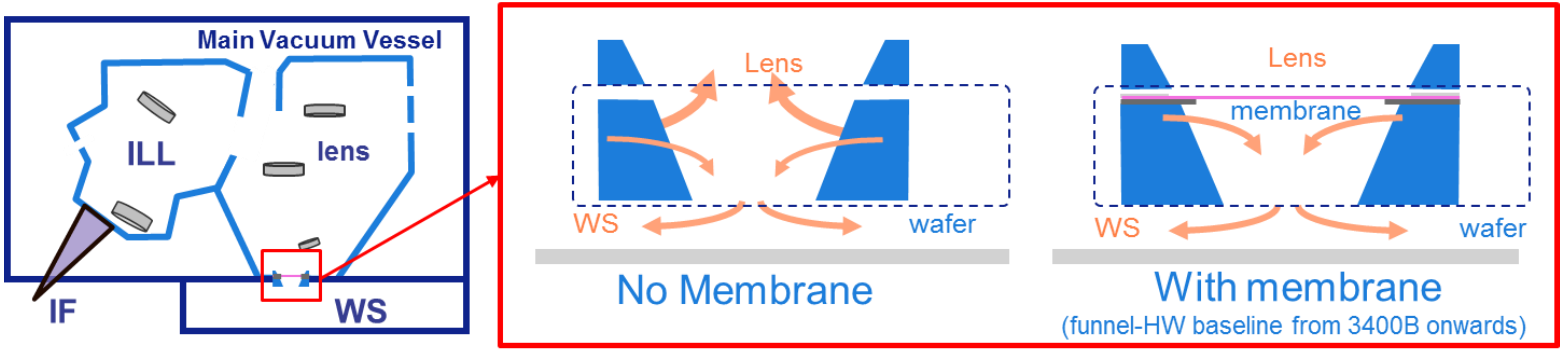


NXE:3400B @ 140W
Power ramp in 4 steps: 95W, 115W, 125W, 140W
22nm PRP-i reticle with pellicle

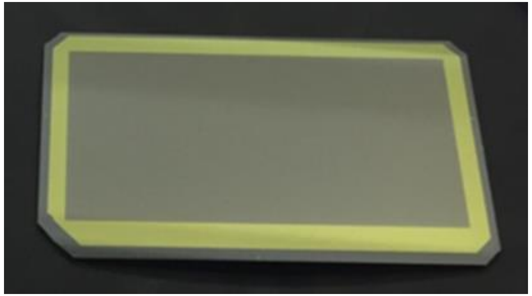
DGL membrane as spectral filter

located at Dynamic Gas Lock (DGL)

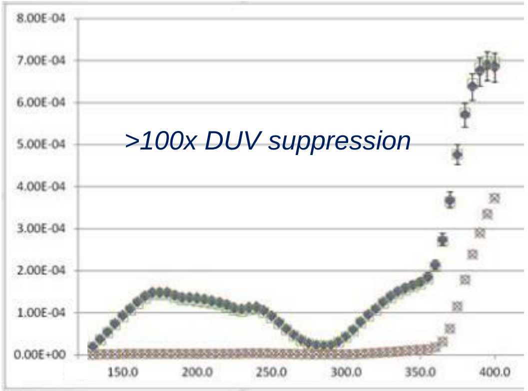
suppresses DUV and IR, plus removes outgassing risk to POB



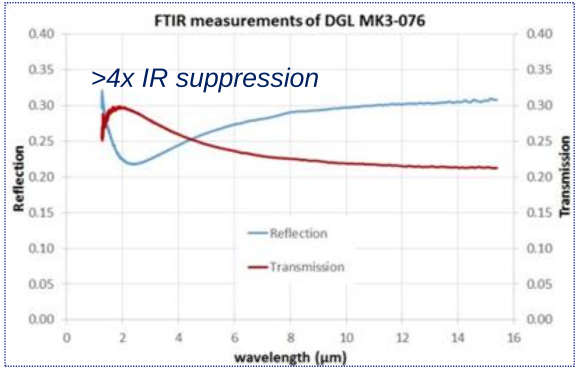
DGL membrane (~ 50 x 25 mm)



Effective DUV and IR suppression



>100x DUV suppression



>4x IR suppression

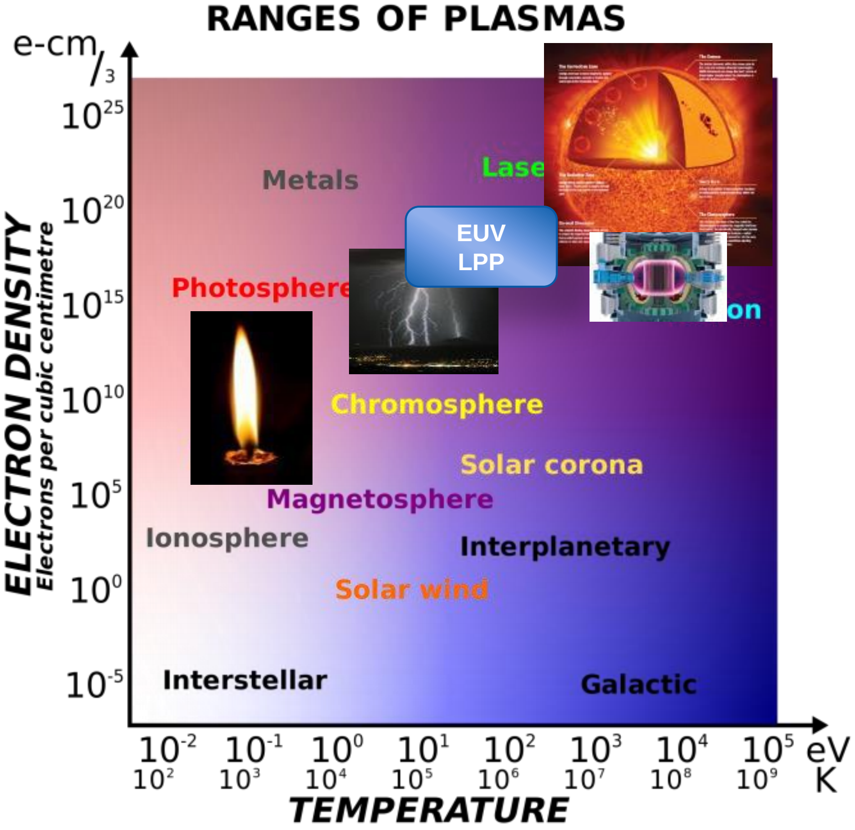
EUV: Principles of Generation

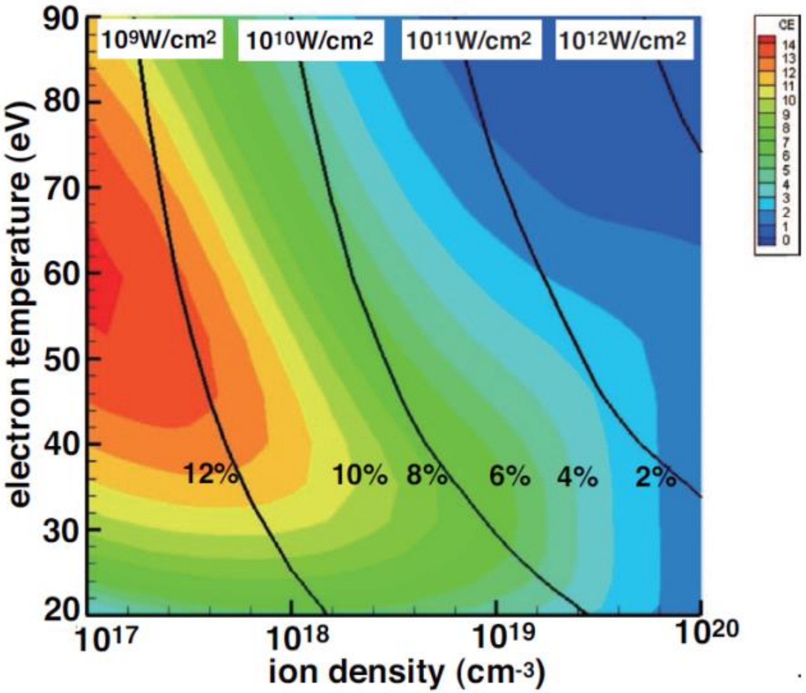
Laser Produced Plasma Density and Temperature

Nishihara et al. (2008)

Ion density ~ $10^{17} – 10^{18}$ #/cm^3

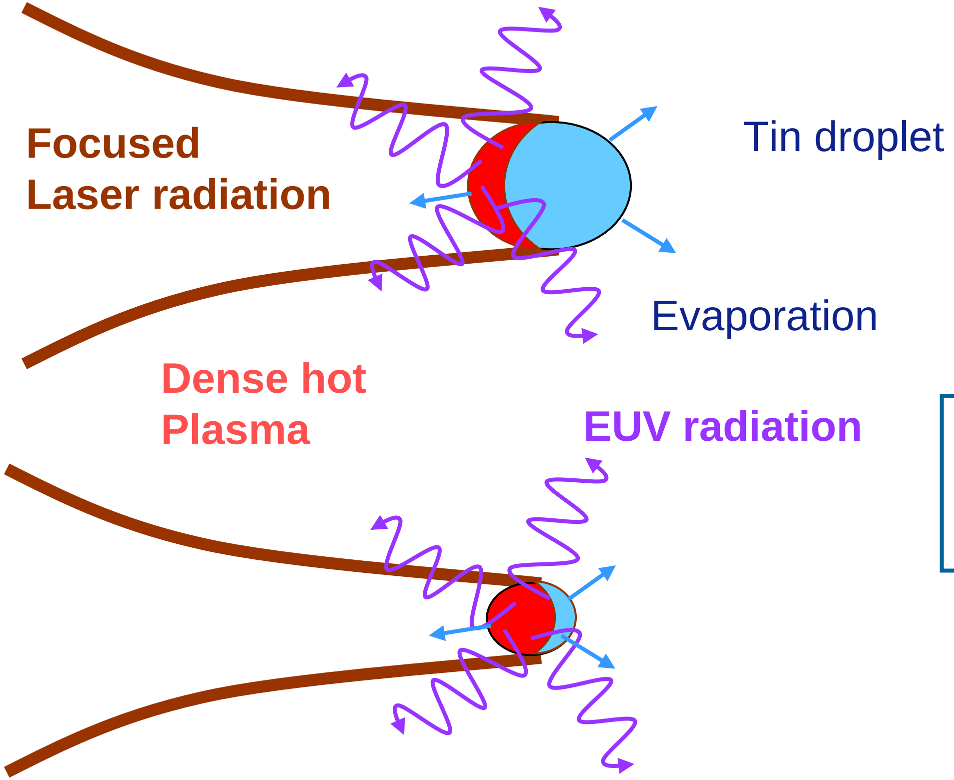
Temperature ~ 30 -100 eV

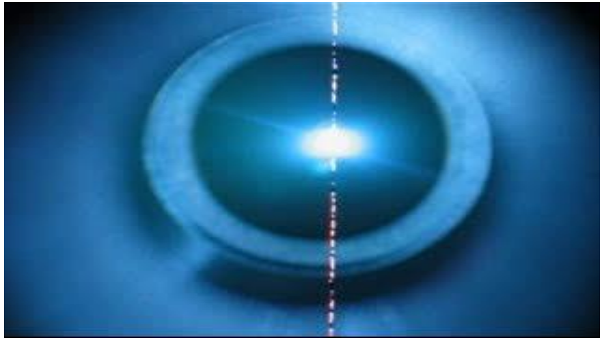




Fundamentals: EUV Generation in LPP

Laser produced plasma (LPP) as an EUV emitter



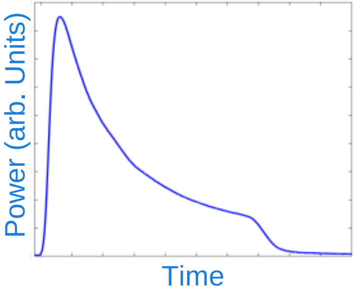


Properties determined by ratio of plasma-to target size, laser pulse energy and droplet diameter

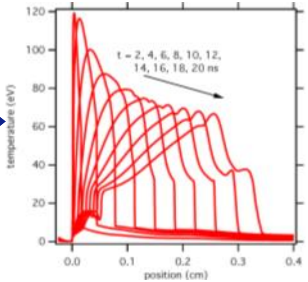
Plasma simulation capabilities

Main-pulse modeling using HYDRA

Main-pulse shape

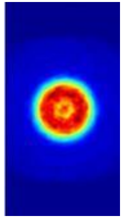


1D:
real pulse shape

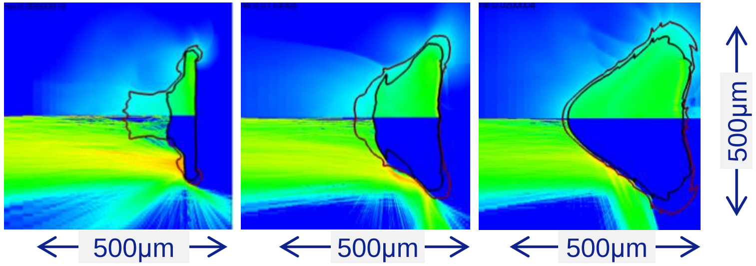


1D simulations are fast and useful for problems that require rapid feedback and less accuracy

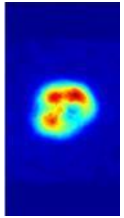
2D:
+ symmeterized beam profile

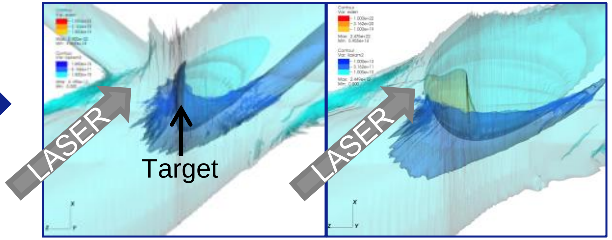


Electron density (top half) with laser light (bottom half)



3D:
+ real asymmetric profile





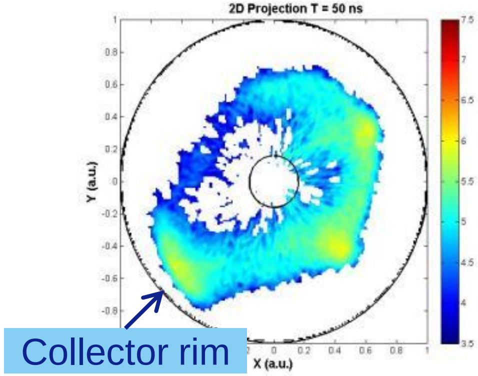
2D and 3D simulations are run for the full duration of the Main pulse. Results include temperature, electron density, spectral emission, etc.

Sn target using a real irradiance distribution

Simulation of the EUV source

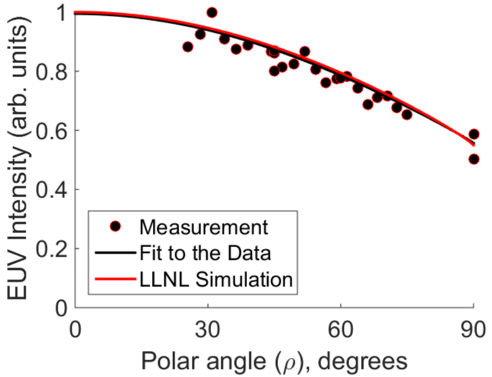
The plasma code’s outputs were processed to produce synthetic source data. The comparison to experiments helps to validate the code and understand it’s accuracy.

Reflected laser modeling

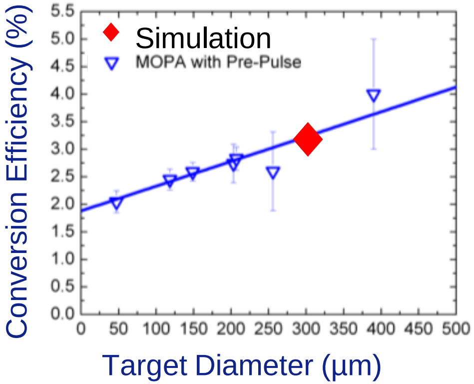


Collector rim

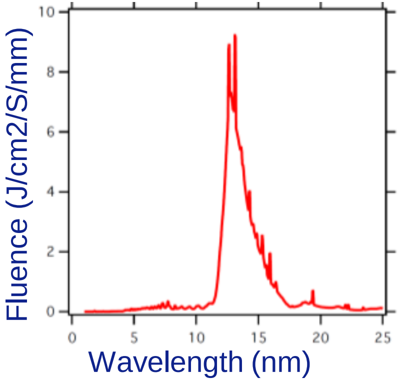
Emission and debris anisotropy



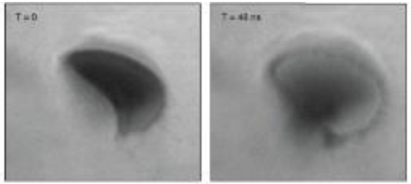
Conversion Efficiency



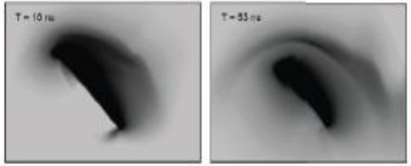
Simulated EUV spectra



Measured Shadowgrams



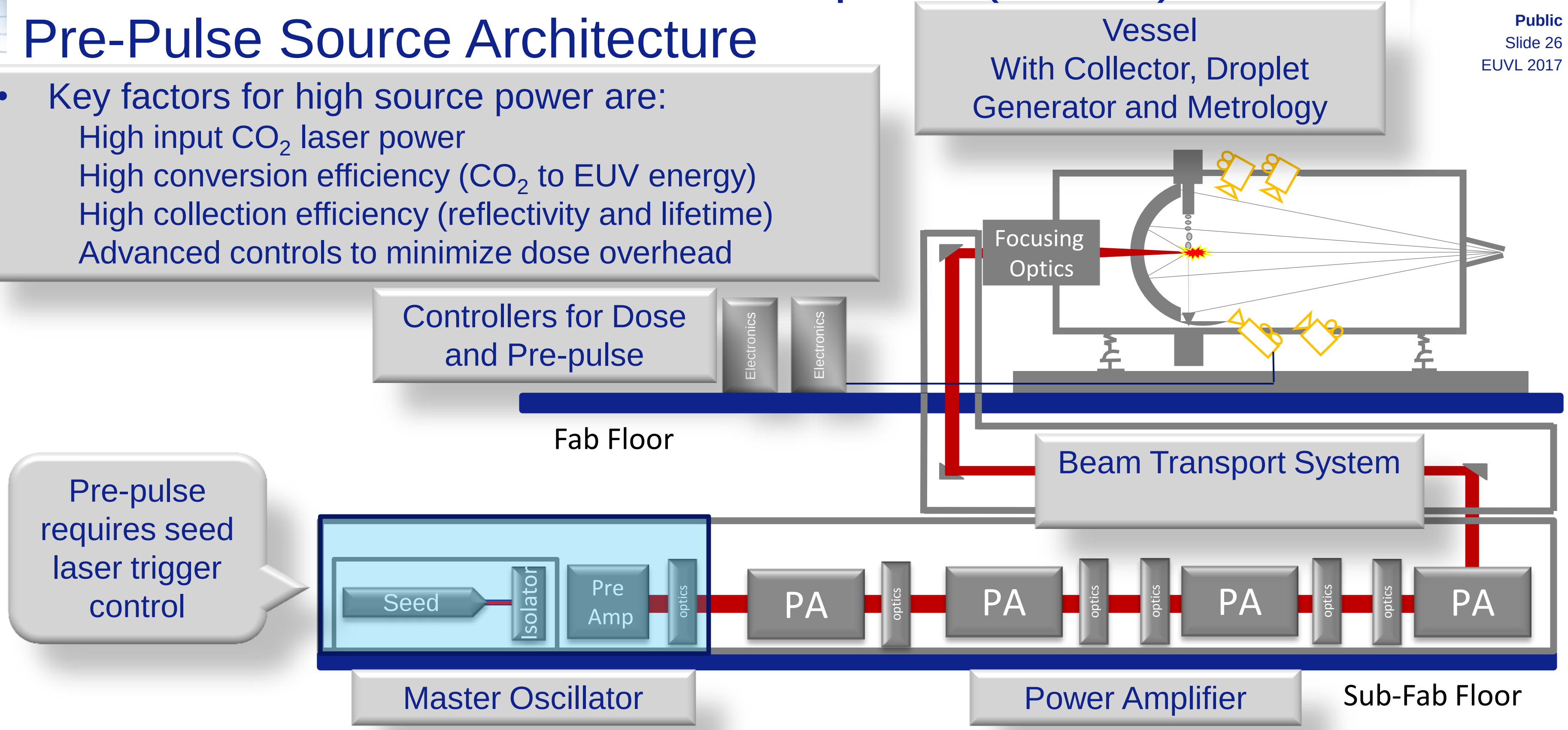
Simulated Shadowgrams



EUV Source: Architecture and Operation Principles

LPP: Master Oscillator Power Amplifier (MOPA) Pre-Pulse Source Architecture

- Key factors for high source power are:
  - High input CO_2 laser power
  - High conversion efficiency (CO_2 to EUV energy)
  - High collection efficiency (reflectivity and lifetime)
  - Advanced controls to minimize dose overhead



Vessel
With Collector, Droplet
Generator and Metrology

Controllers for Dose
and Pre-pulse

Beam Transport System

Pre-pulse requires seed laser trigger control

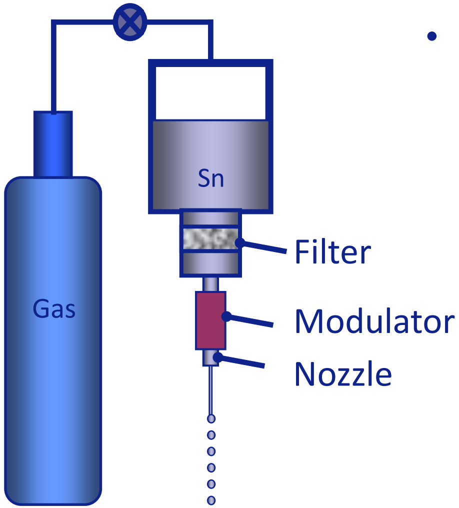
Master Oscillator

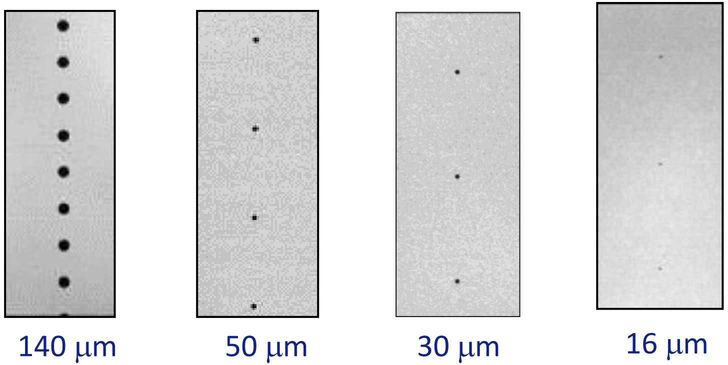
Power Amplifier

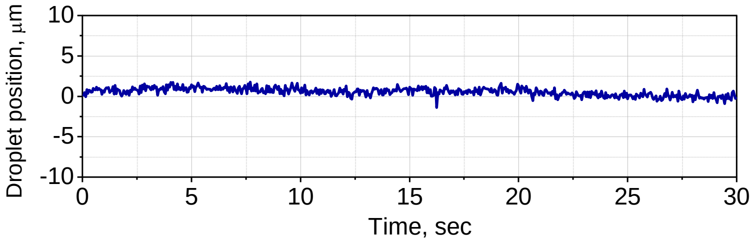
EUV power
(source/scanner interface, [W])
$\propto$
CO_2 power [W]
*
Conversion Efficiency [%]
*
1 – Dose Overhead [%]

Droplet Generator: Principle of Operation

- Tin is loaded in a vessel & heated above melting point
- Pressure applied by an inert gas
- Tin flows through a filter prior to the nozzle
- Tin jet is modulated by mechanical vibrations



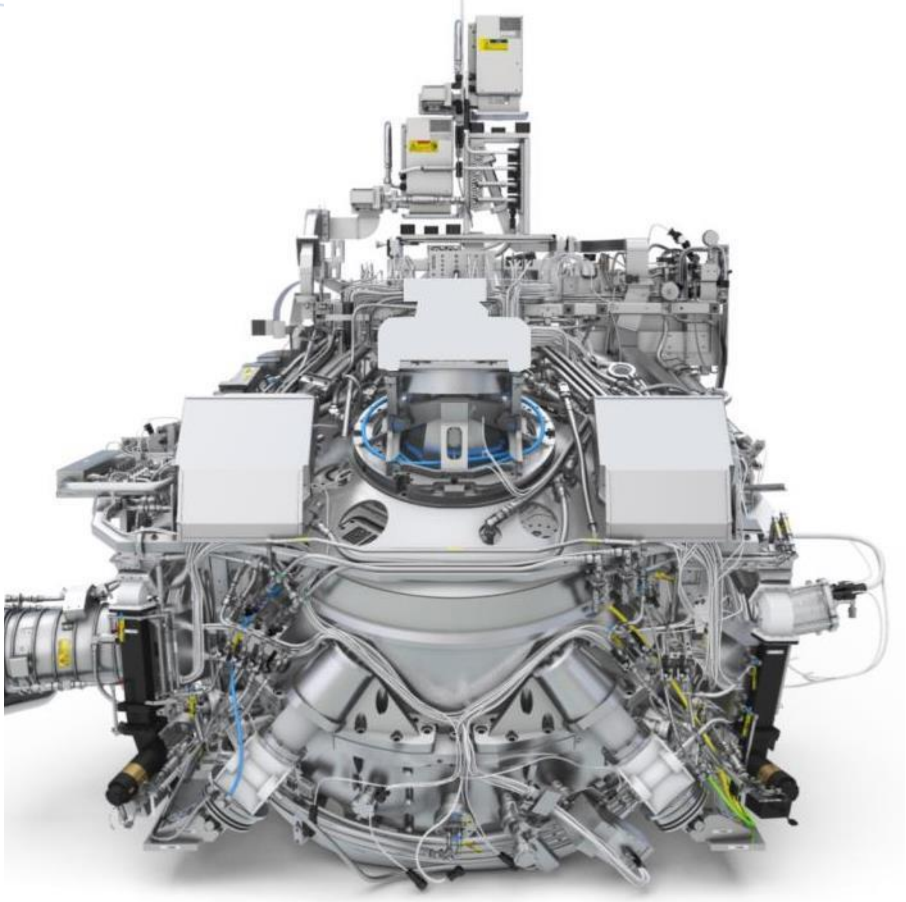


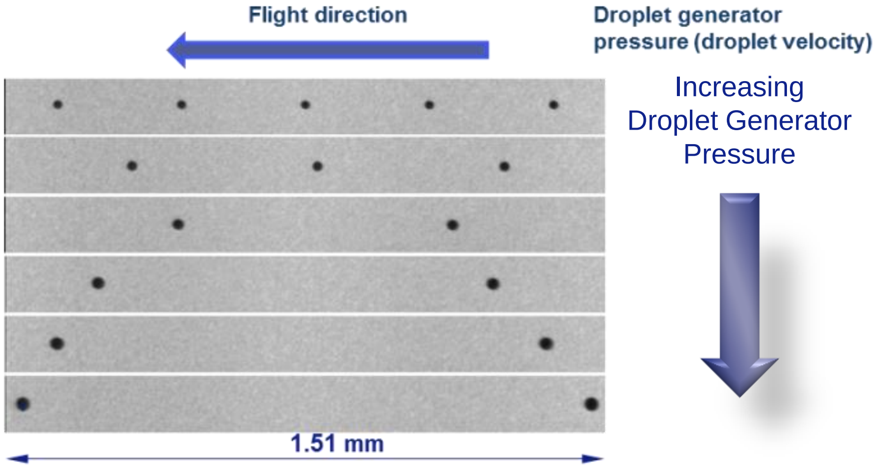


Short term droplet position stability σ~1µm

NXE:3xx0 EUV Source: Main modules

Populated vacuum vessel with tin droplet generator and collector

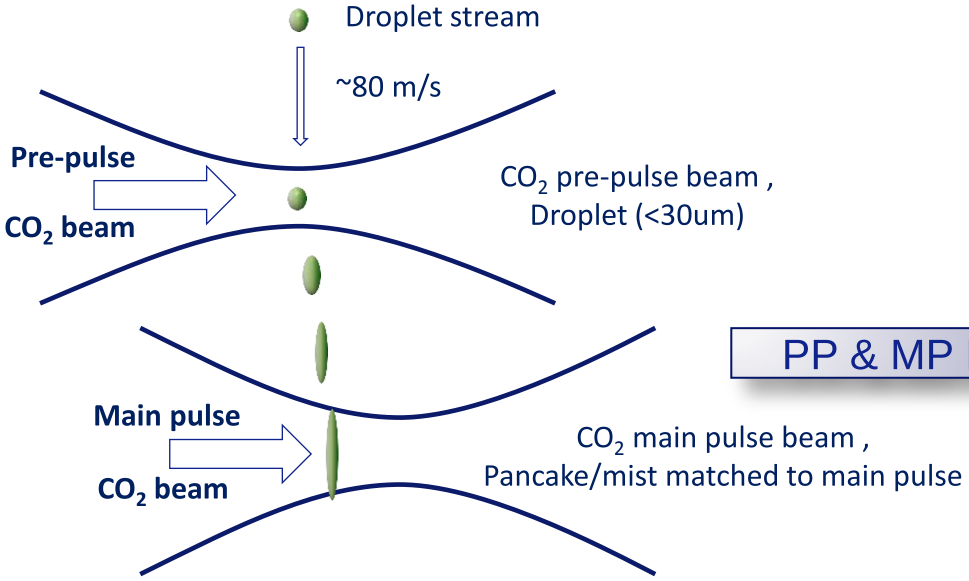




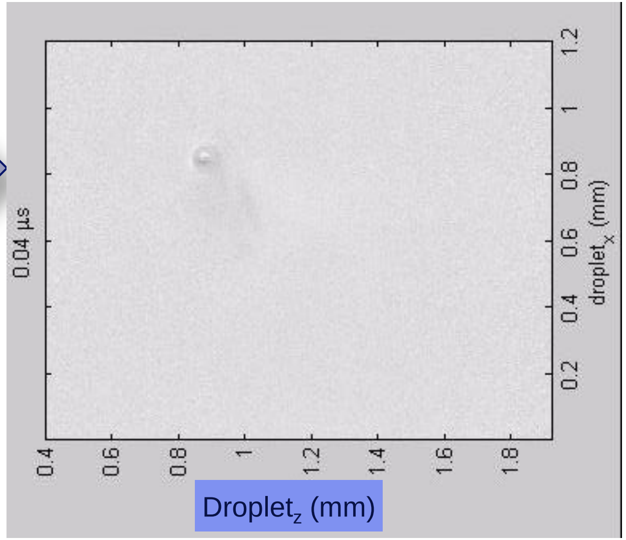
Droplet Spacing at 80 kHz

EUV Source: MOPA + Pre-Pulse

MOPA = Master Oscillator Power Amplifier
PP = Pre-Pulse
MP = Main Pulse



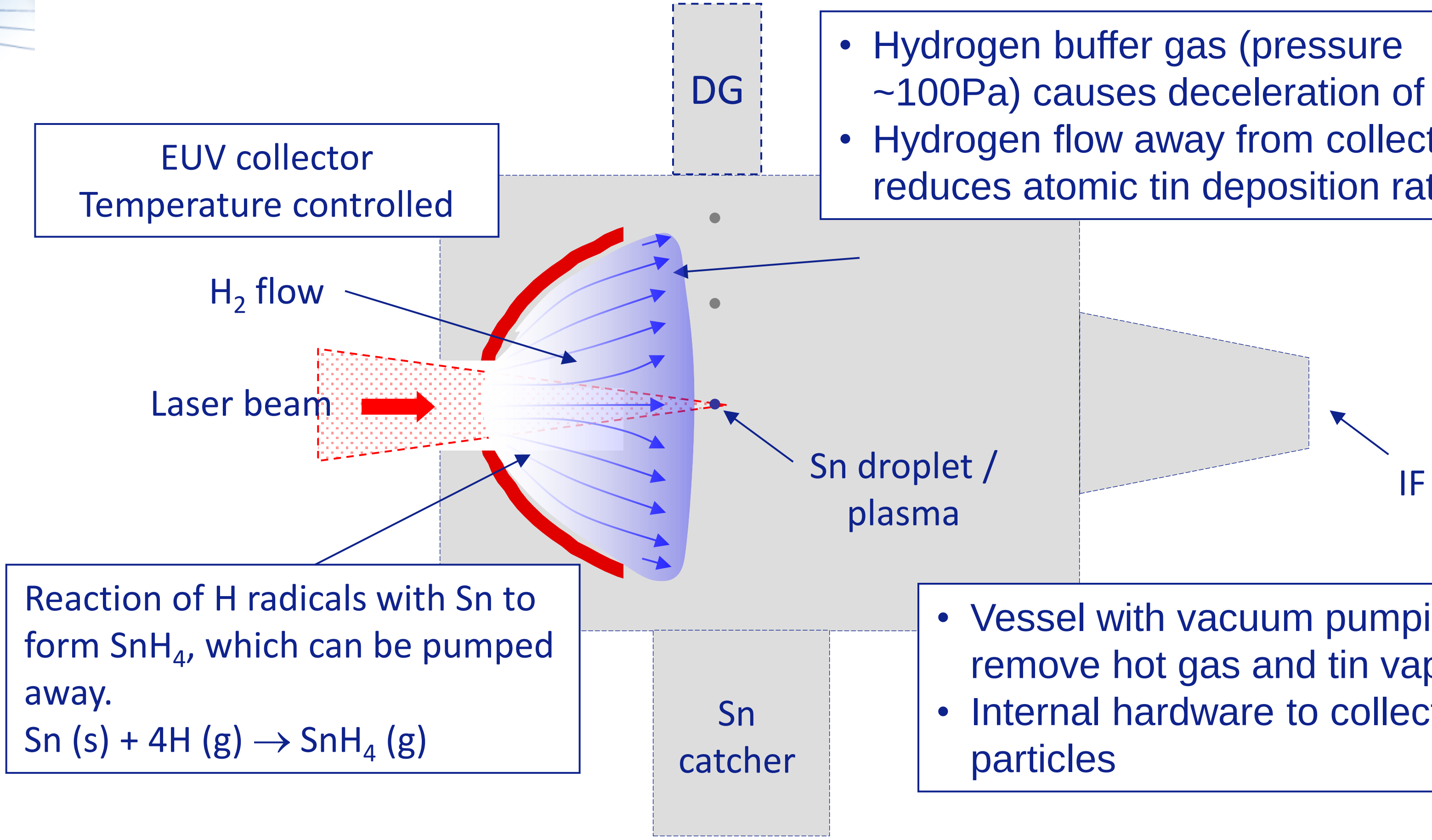
PP & MP Laser



Pre-pulse transforms tin droplet into
"pancake/mist" that matches
CO_2 main pulse beam profile

>5% conversion efficiency achieved

Collector Protection by Hydrogen Flow



EUV collector
Temperature controlled

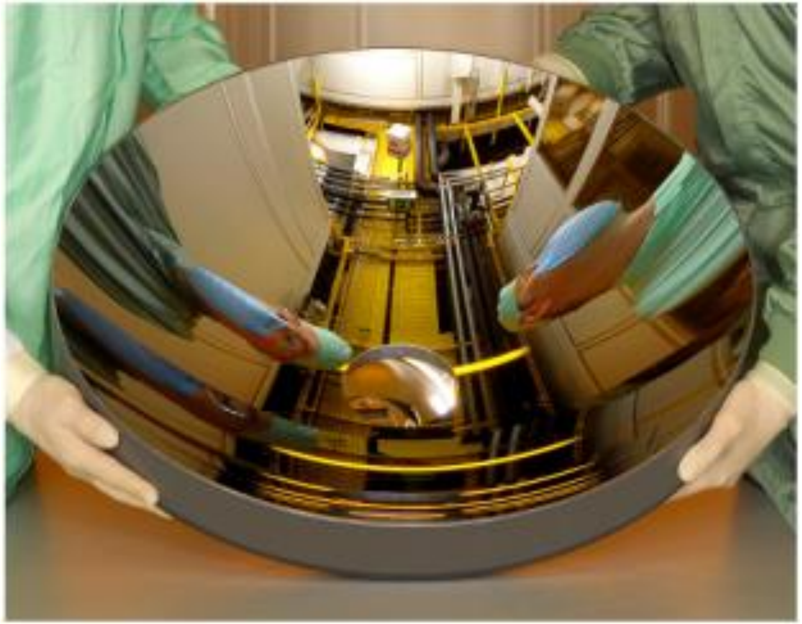
- Hydrogen buffer gas (pressure ~100Pa) causes deceleration of ions
- Hydrogen flow away from collector reduces atomic tin deposition rate

Reaction of H radicals with Sn to form SnH_4, which can be pumped away.
$Sn\ (s) + 4H\ (g) \rightarrow SnH_4\ (g)$

- Vessel with vacuum pumping to remove hot gas and tin vapor
- Internal hardware to collect micro particles

EUV Collector: Normal Incidence

- Ellipsoidal design
    - Plasma at first focus
    - Power delivered to exposure tool at second focus (intermediate focus)
- Wavelength matching across the entire collection area



Normal Incidence Graded
Multilayer Coated Collector

Productivity increases via source availability

Secured EUV power is matched with increasing availability

$$\boxed{\text{Productivity} = \text{Throughput}(\propto \text{EUV Power}) \times \text{Availability}}$$

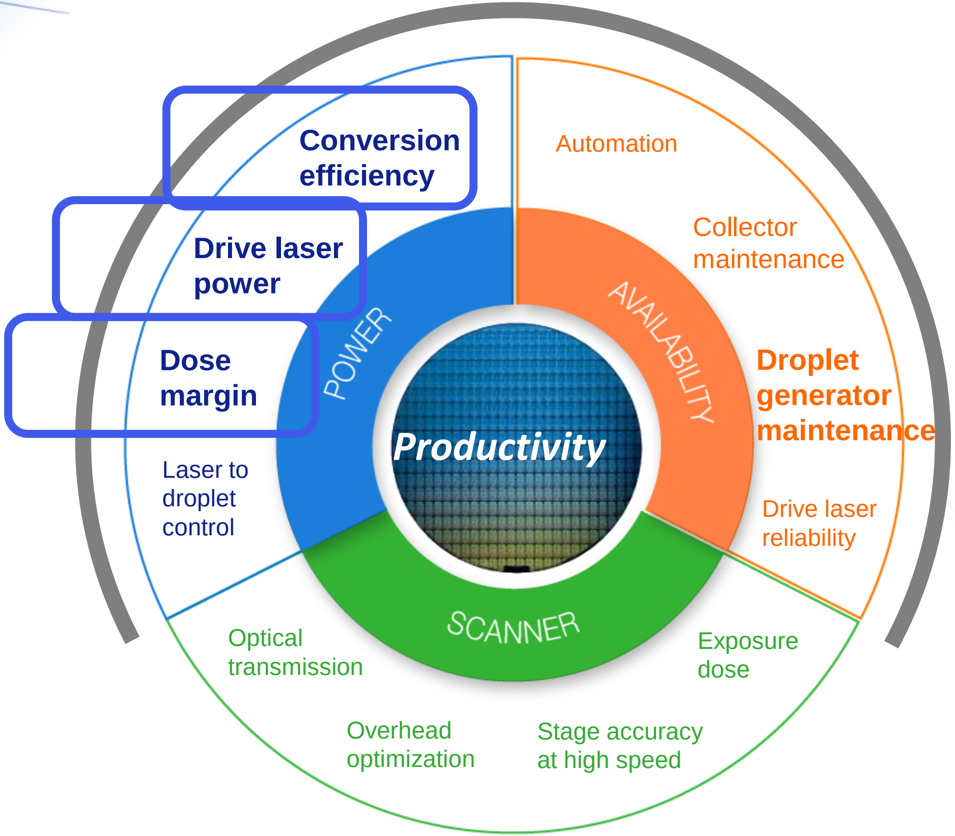
$$\boxed{\text{EUV Power}= (\text{CO}_2\ \underbrace{\text{laser power} \times \text{CE} \times \text{transmission})}_{\text{Raw EUV power}}*(1\text{-dose overhead})}$$

Source power **from 10 W to > 250 W**	Drive laser power	from 20 to 40 kW
	Conversion efficiency (CE)	from 2 to 6% (Sn droplet)
	Dose overhead	from 50 to 10%
	Optical transmission	
Source availability	Automation	
	Collector protection	
	Droplet generator reliability & lifetime	
	Drive laser reliability	

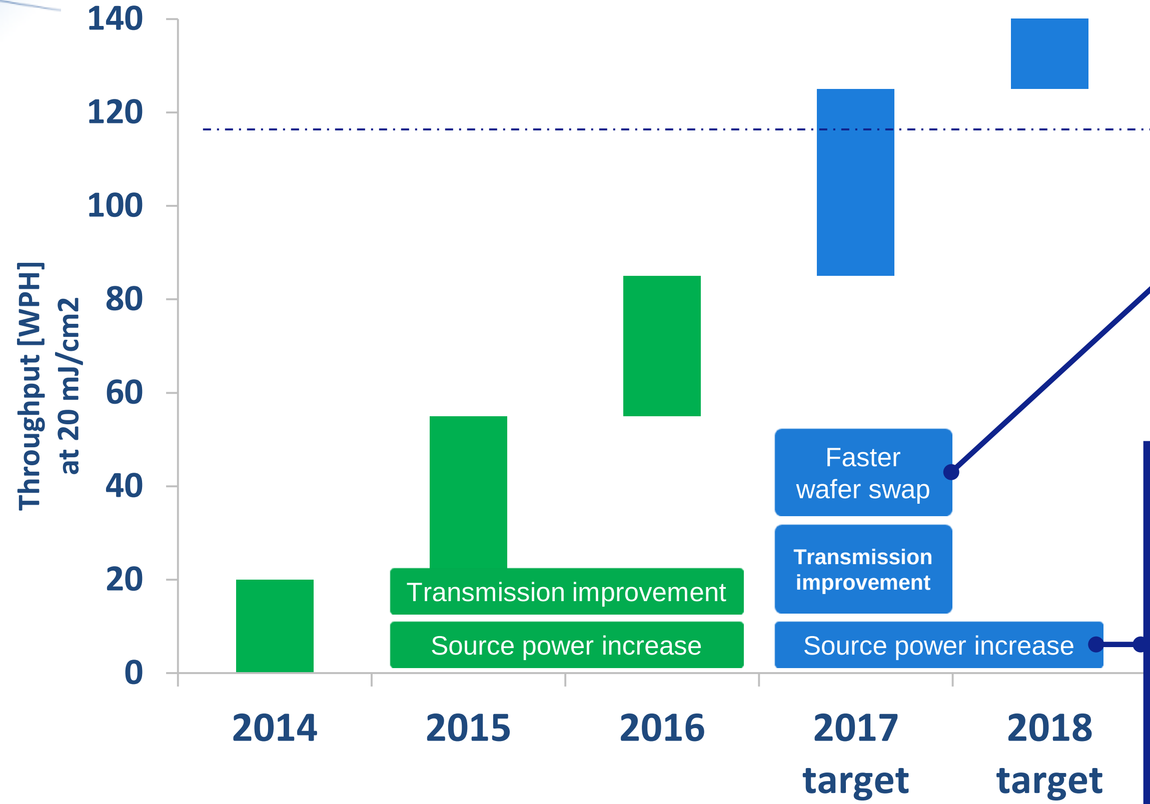
EUV Sources in the Field

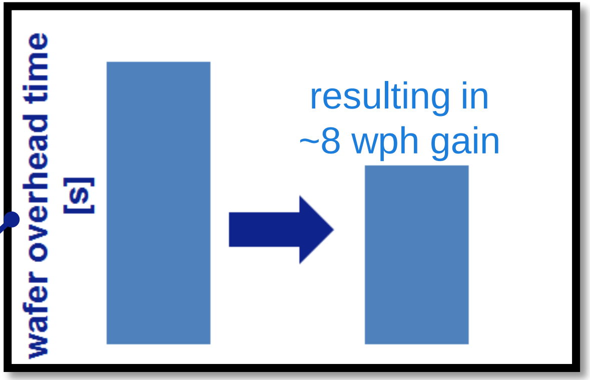
Productivity targets for HVM

Source contribution to productivity

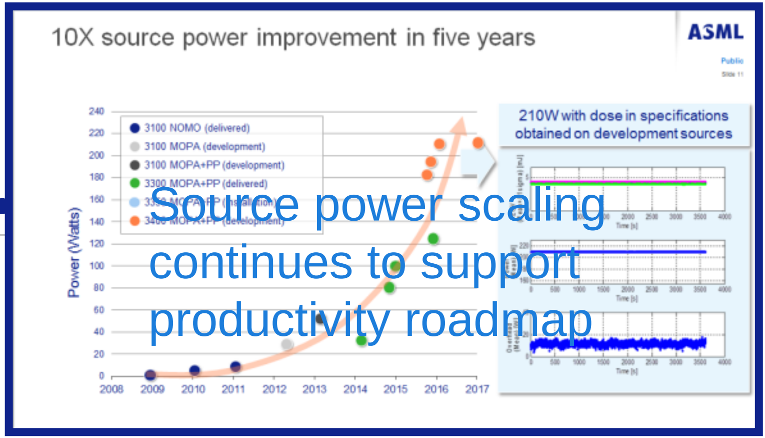


Productivity roadmap towards >125 WPH in place





resulting in ~8 wph gain



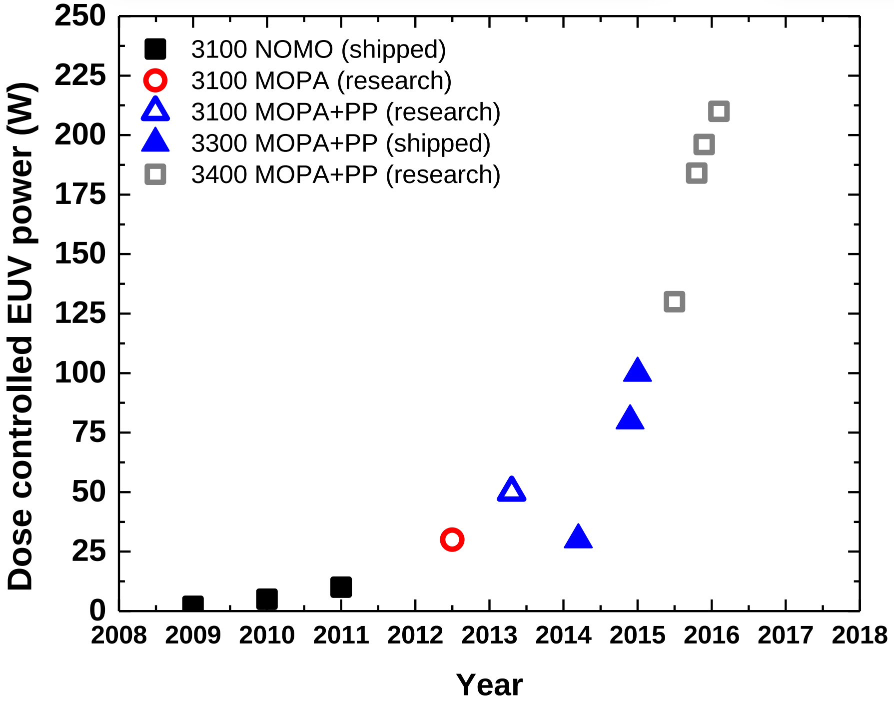
10X source power improvement in five years

210W with dose in specifications obtained on development sources

Source power scaling continues to support productivity roadmap

Progress for 2017: >205W demonstrated

EUV power (source/scanner interface, [W]) $\propto$ **CO_2 power [W]** * **Conversion Efficiency [%]** * **1 – Dose Overhead [%]**



>205W is now demonstrated, shipping planned end of 2017

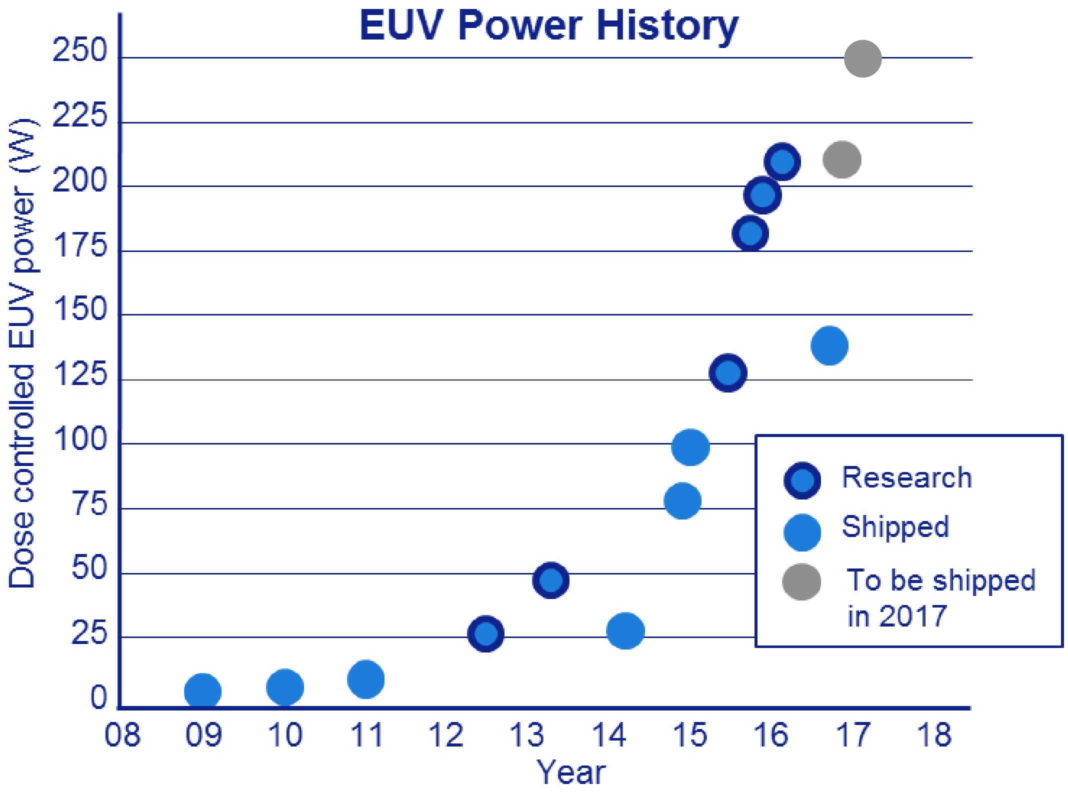
- Increase average and peak laser power
- Enhanced isolation technology

- Advanced target formation technology

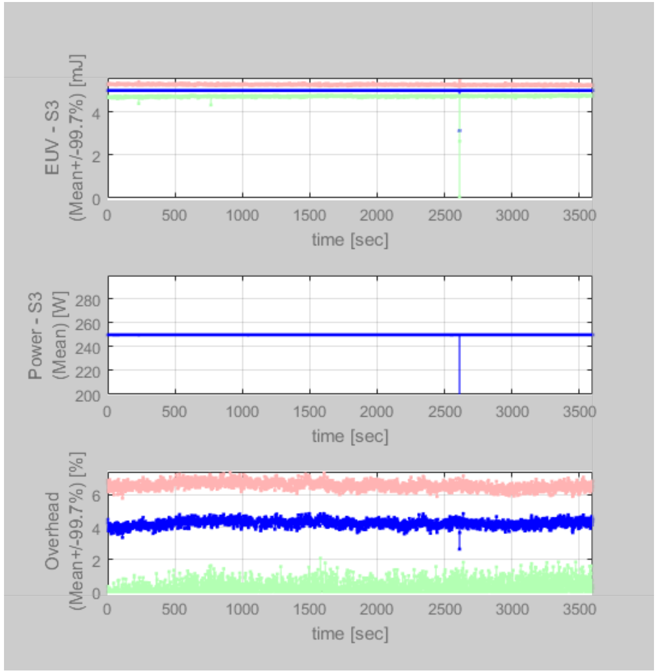
- Improved dose-control technique

Source power: 250W demonstrated

10x improvement in five years

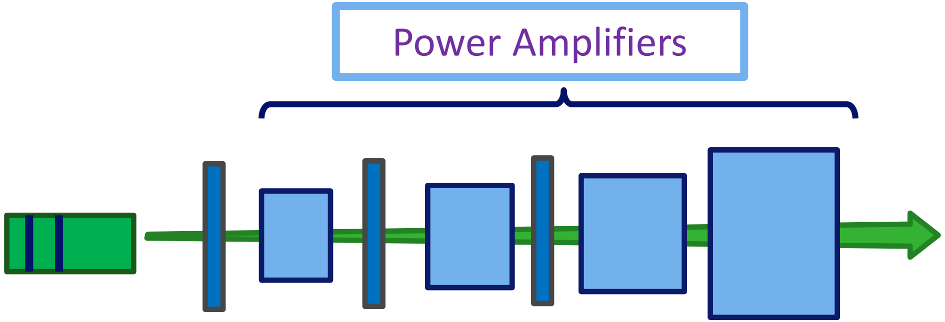


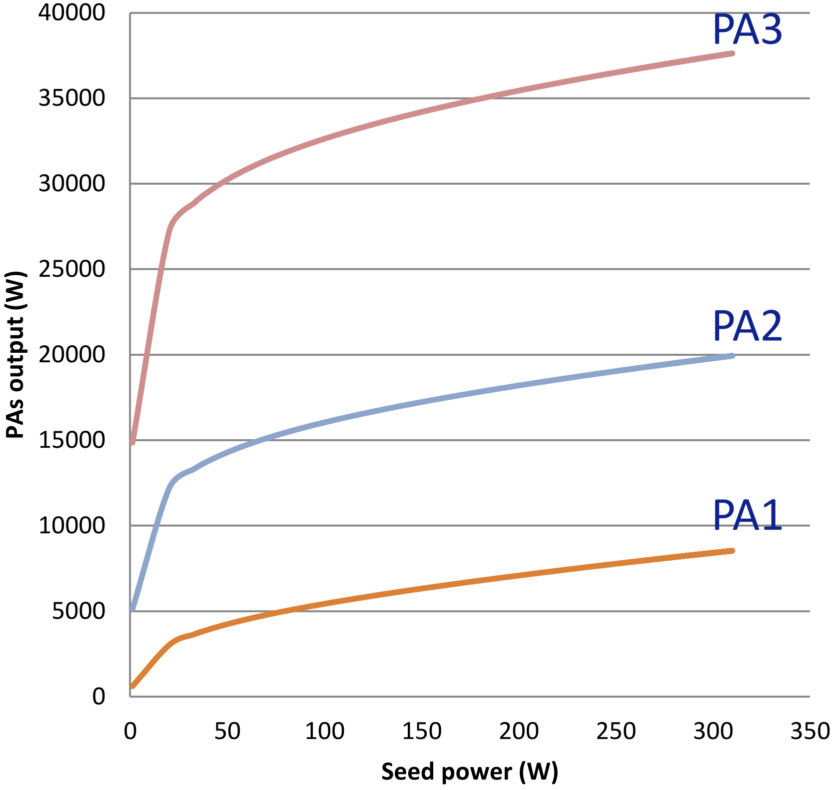
250W with dose in specifications obtained on development source



Power Amplifier Chain Increases CO_2 Power

Good beam quality for gain extraction and EUV generation

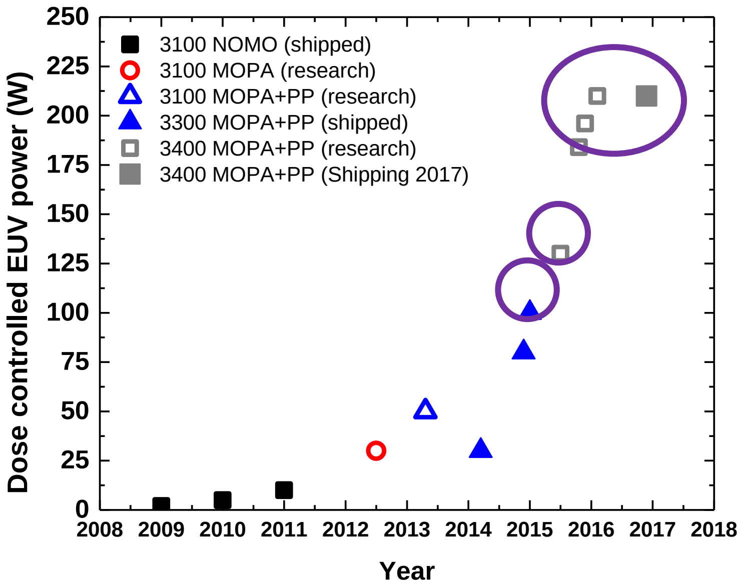


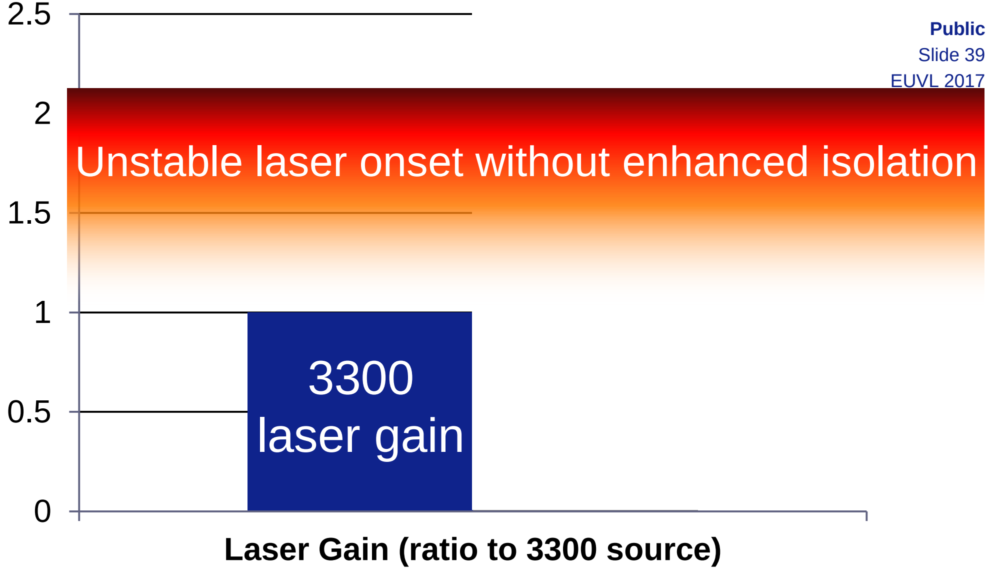


Key technologies:

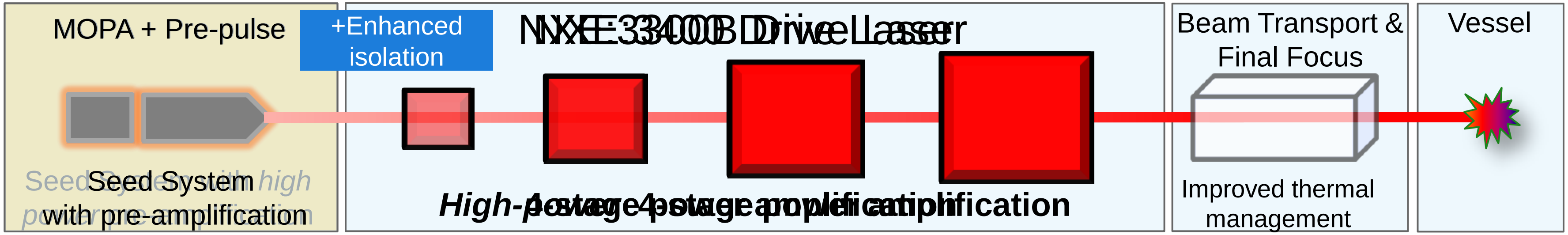
1. Drive laser with higher power capacity
2. Gain distribution inside amplification chain
3. Mode-matching during beam propagation
4. Isolation between amplifiers
5. Metrology, control, and automation

Scaling laser power requires laser isolation advances





From NXE:3300 to NXE:3400, enhanced isolation gives stable >2x increase laser gain



MOPA + Pre-pulse

+Enhanced isolation

Seed System with high power pre-amplification

Seed System with pre-amplification

NXE:3300B Drive Laser

NXE:3400B Drive Laser

High-power 4-stage amplification

4-stage amplification

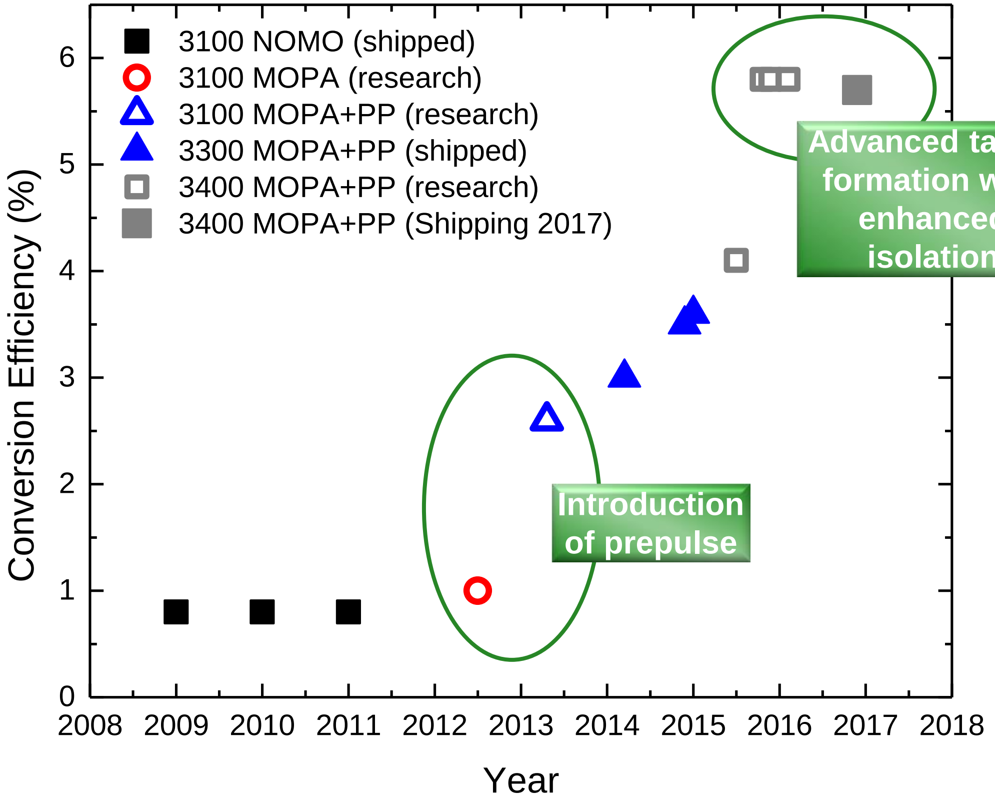
Beam Transport & Final Focus

Improved thermal management

Vessel

Enhanced isolation leads to >205W EUV power

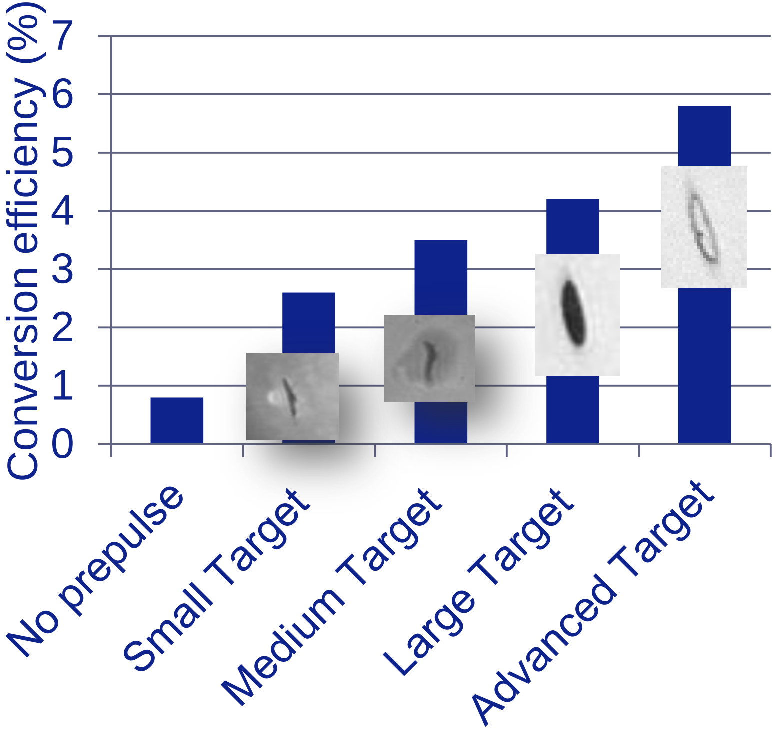
via advanced target formation for high CE



Advanced target formation with enhanced isolation

Introduction of prepulse

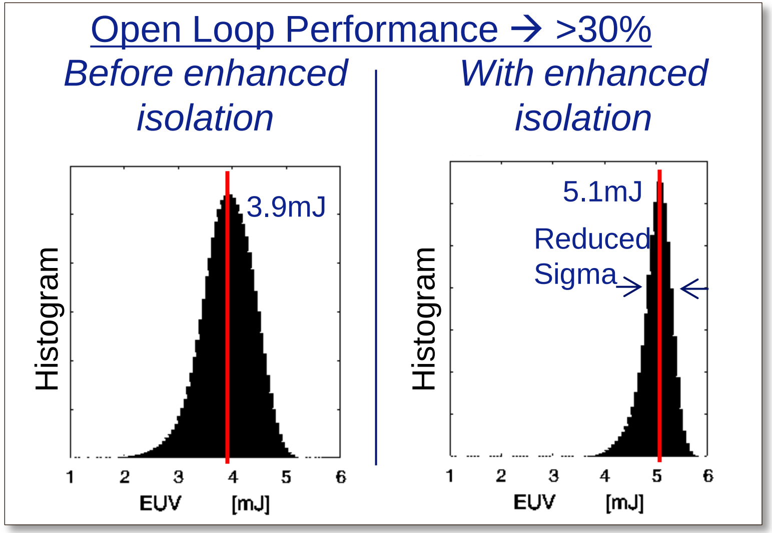
Conversion Efficiency vs target type

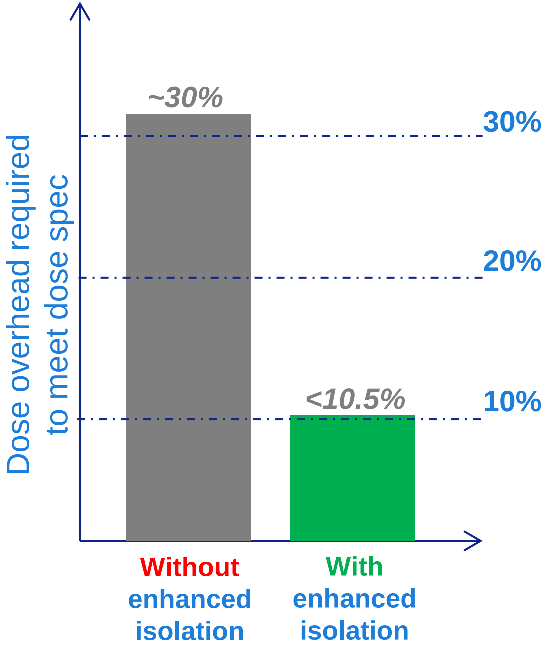


Enhanced isolation improves EUV performance

Benefits of enhanced isolation:

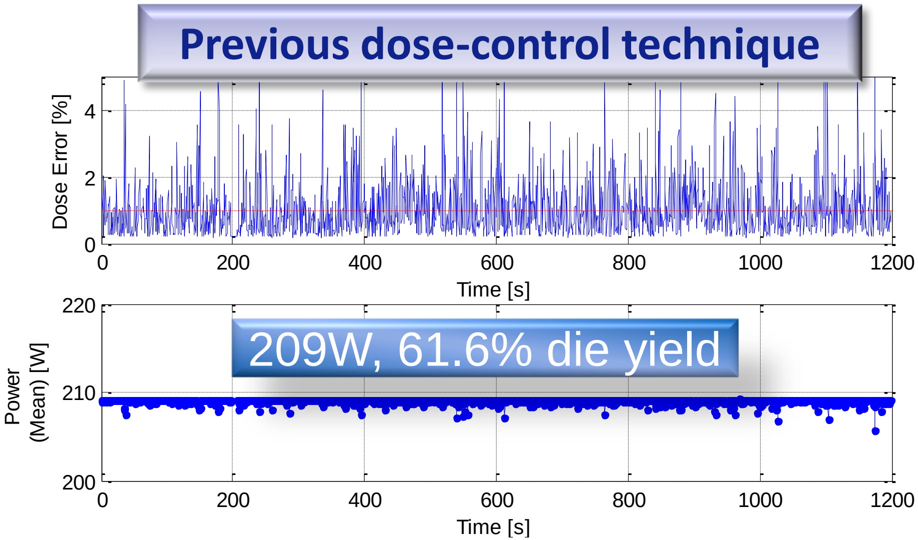
- **Higher, stable CO_2 laser power → lower dose overhead**
- **High conversion efficiency operation → higher pulse energy**

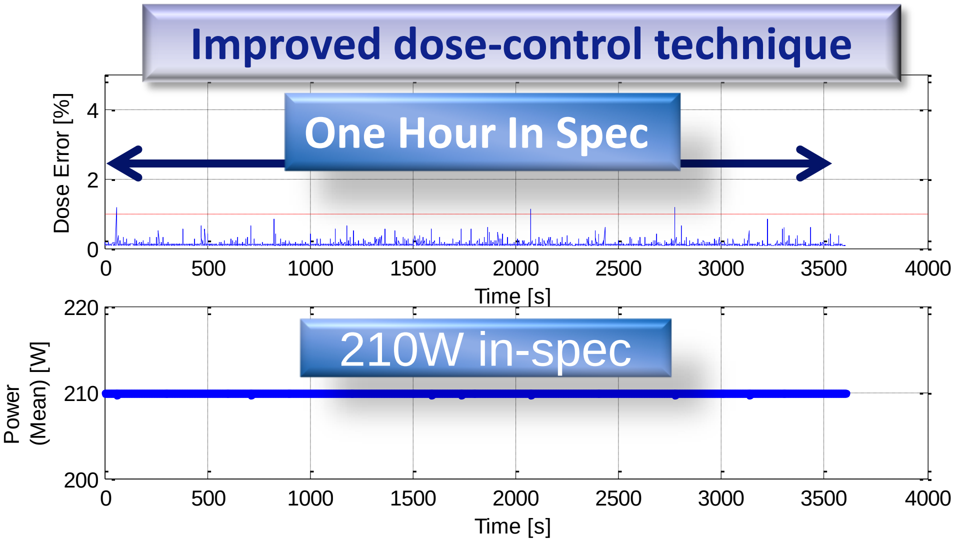




Comparing two dose-control techniques **at 210W**:

higher in-spec power with improved dose-control technique

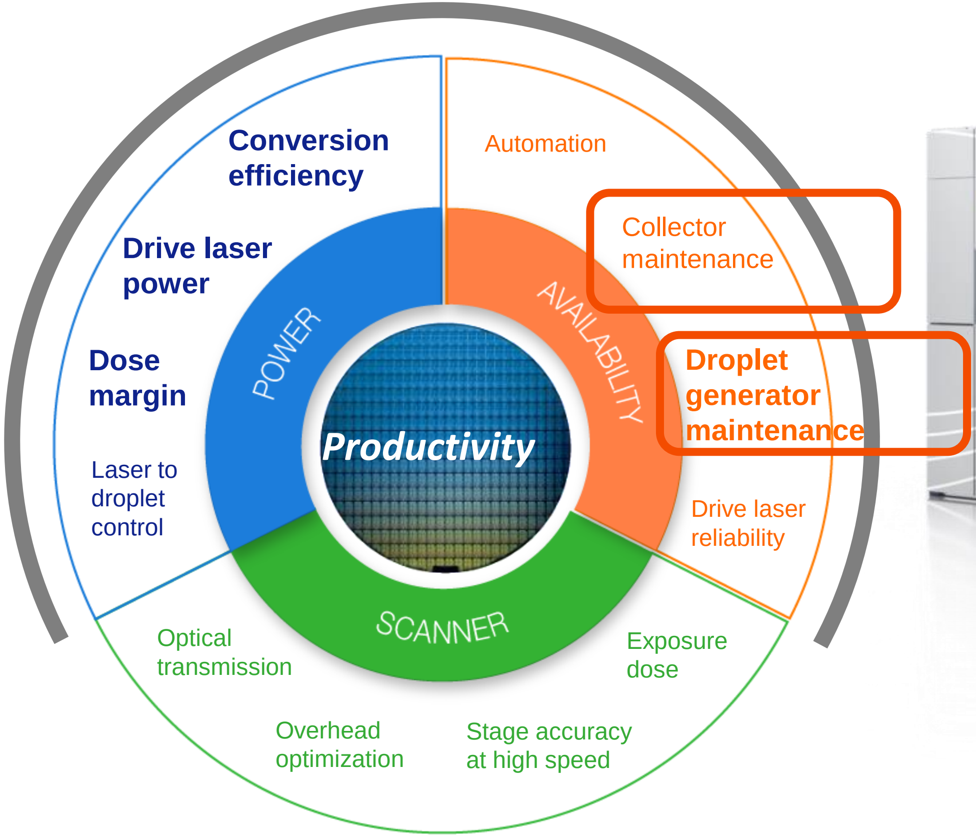




On the same EUV source, back-to-back performance comparing previous and improved dose-control techniques demonstrates higher in-spec power can be delivered with reduced overhead

Productivity targets for HVM

Source contribution to productivity

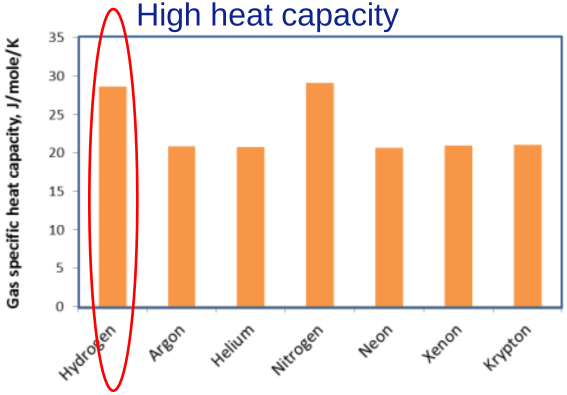


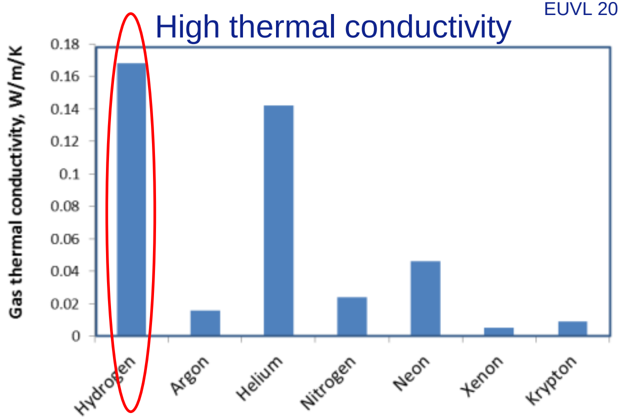
Hydrogen gas central to tin management strategy

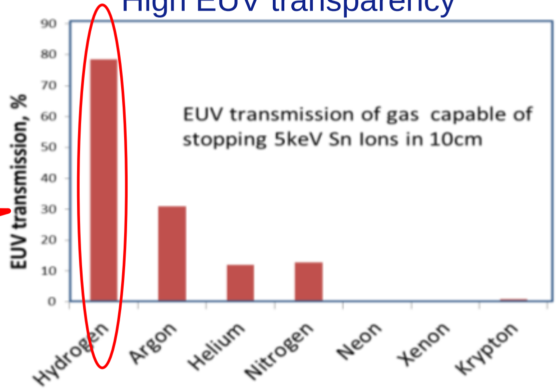
Requirements for buffer gas:

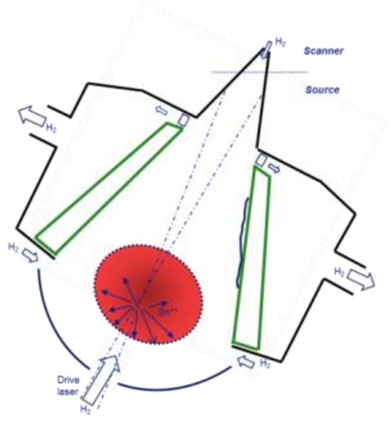
- **Stopping fast ions (with high EUV transparency)**
- **Heat transport**
- **Robust against morphology**
- **Sn etching capability**

Hydrogen performs well for all these tasks!


High heat capacity


High thermal conductivity

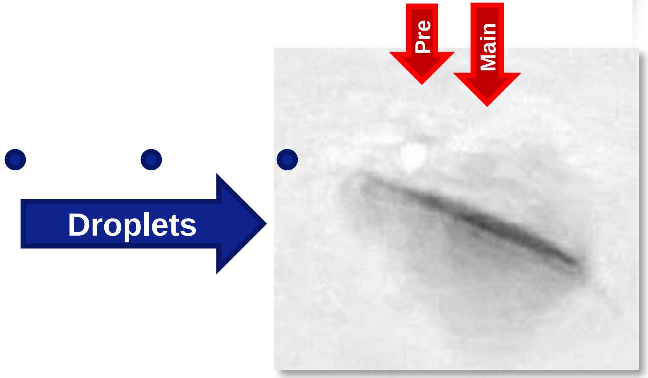

High EUV transparency

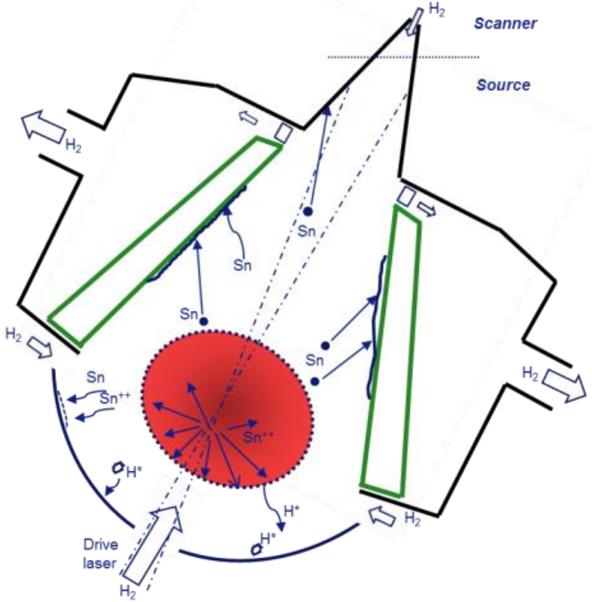


Primary debris

Primary debris – directly from plasma and before collision with any surface:

- Heat and momentum transfer into surrounding gas
  - Kinetic energy and momentum of stopped ions
  - Absorbed plasma radiation
- Sn flux onto collector
  - Diffusion of stopped ions
  - Sn vapor
  - Sn micro-particles





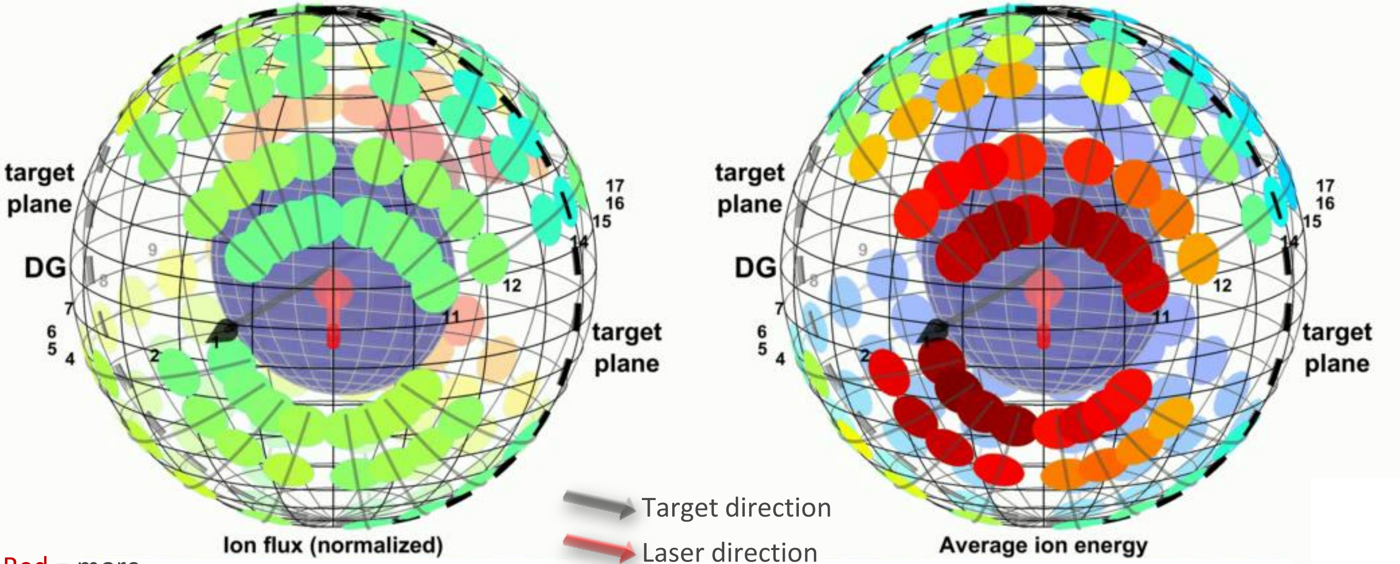
Sn → Sn vapor (diffusion debris)

Sn^+ → Fast Sn ions (line of sight debris)

Sn● → Sn particles

3D measurement of fast tin ion distributions

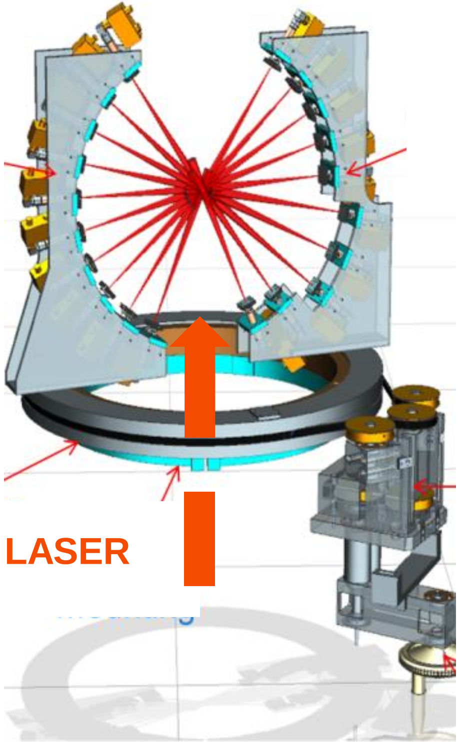
Faraday cups measure tin ion distributions



Red = more
Blue = less

Target direction
Laser direction
FC direction

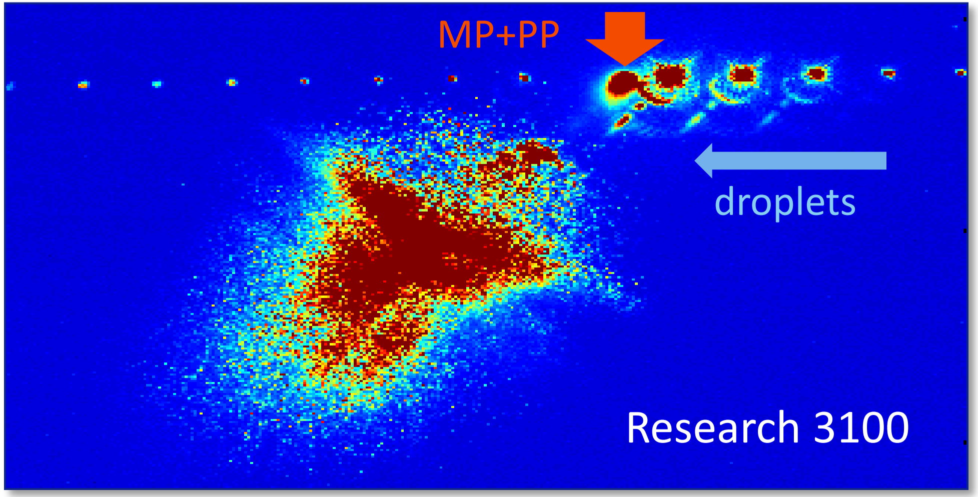
Faraday cup



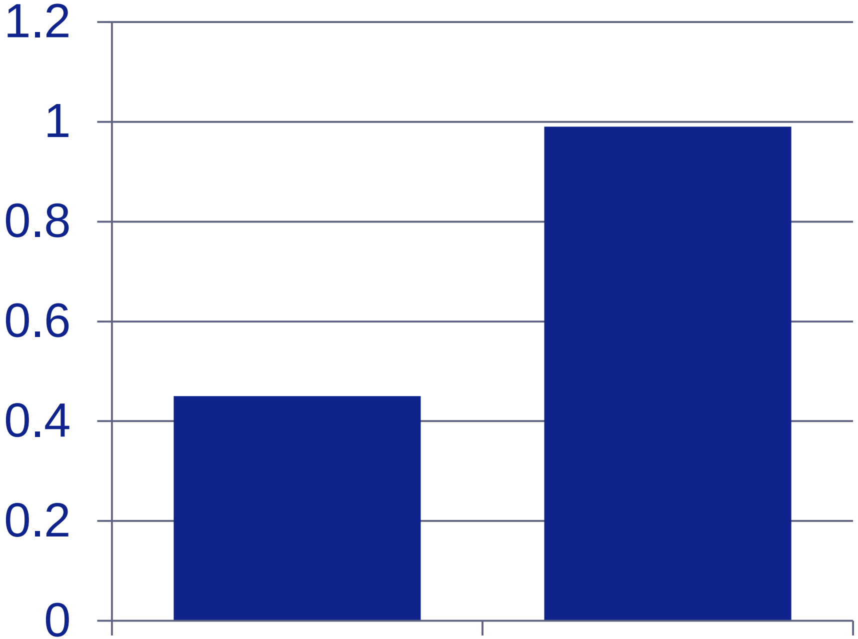
Ion measurements inform H_2 flow requirements for source

Microparticle debris from plasma

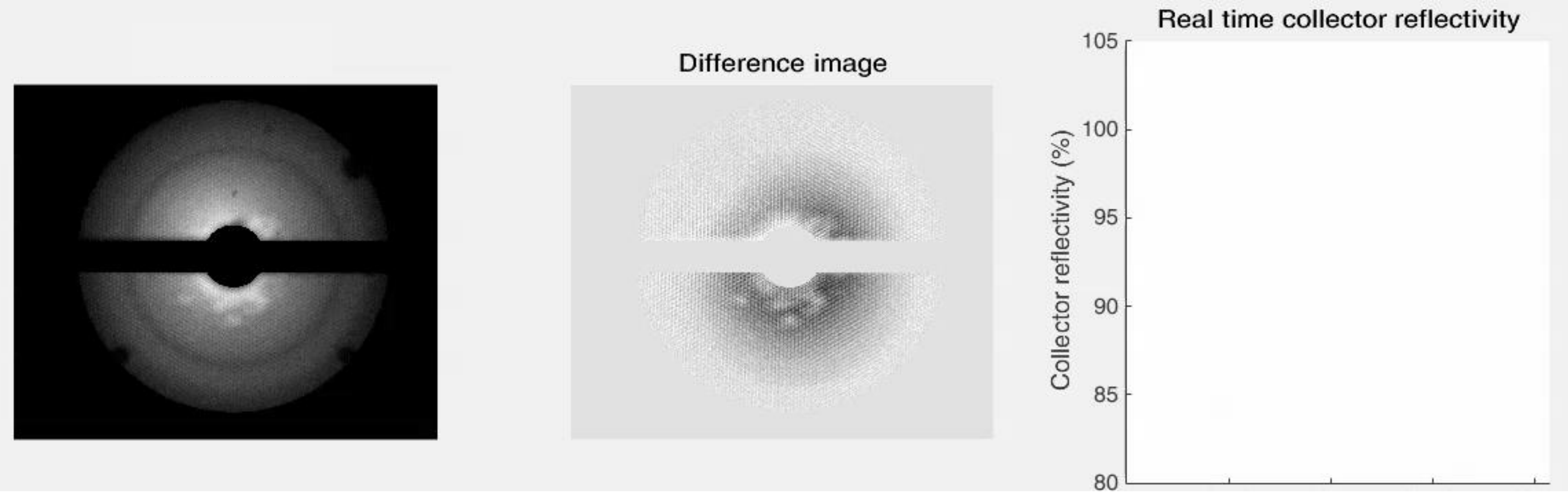
Dark-field scattergraph imaging



Fraction of pulses without microparticle debris



Plasma-generated self-cleaning

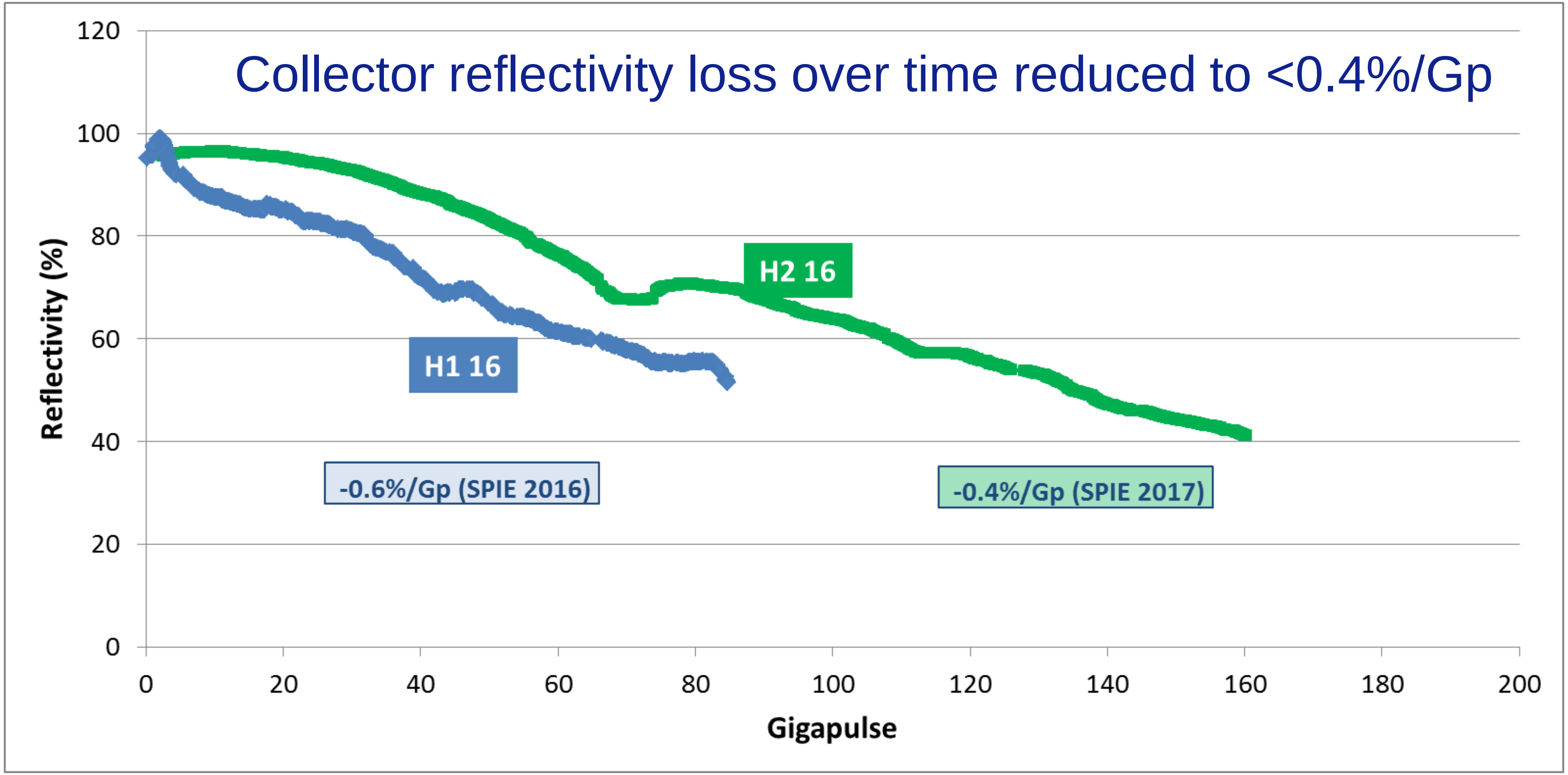


Elemental hydrogen (H*) reacts with tin (Sn) to form Stannane (SnH_4) which is gaseous and is pumped out of the vessel.

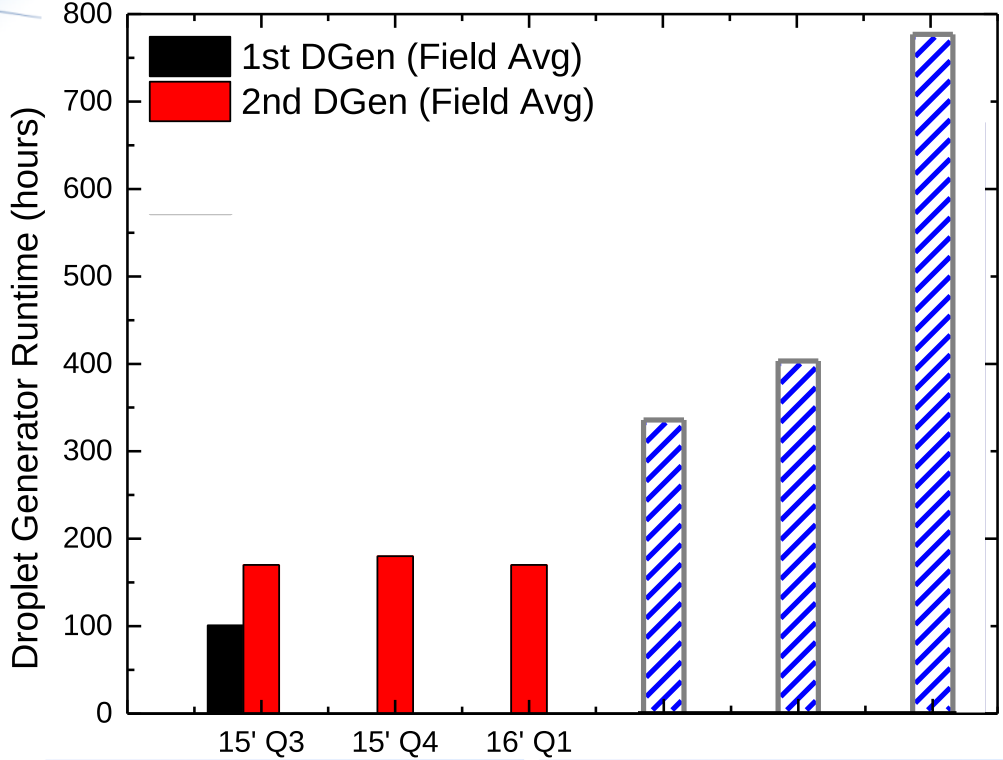
$Sn\ (s) + 4H\ (g) \rightarrow SnH_4\ (g)$

Collector Lifetime Continues to Improve

>100 Gpulse to 50% EUVR



Third generation Droplet Generators: average lifetime increased from 700hrs in 16Q4 to >800hrs 17Q1

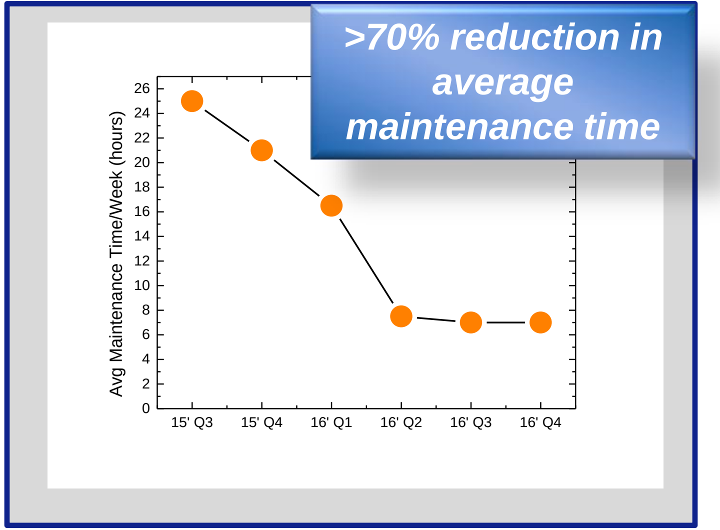


Average lifetime and maintenance time improved by factor ~4

2700 hrs droplet generator runtime demonstrated in the field

3rd generation Droplet generator: long runtime and high reliability

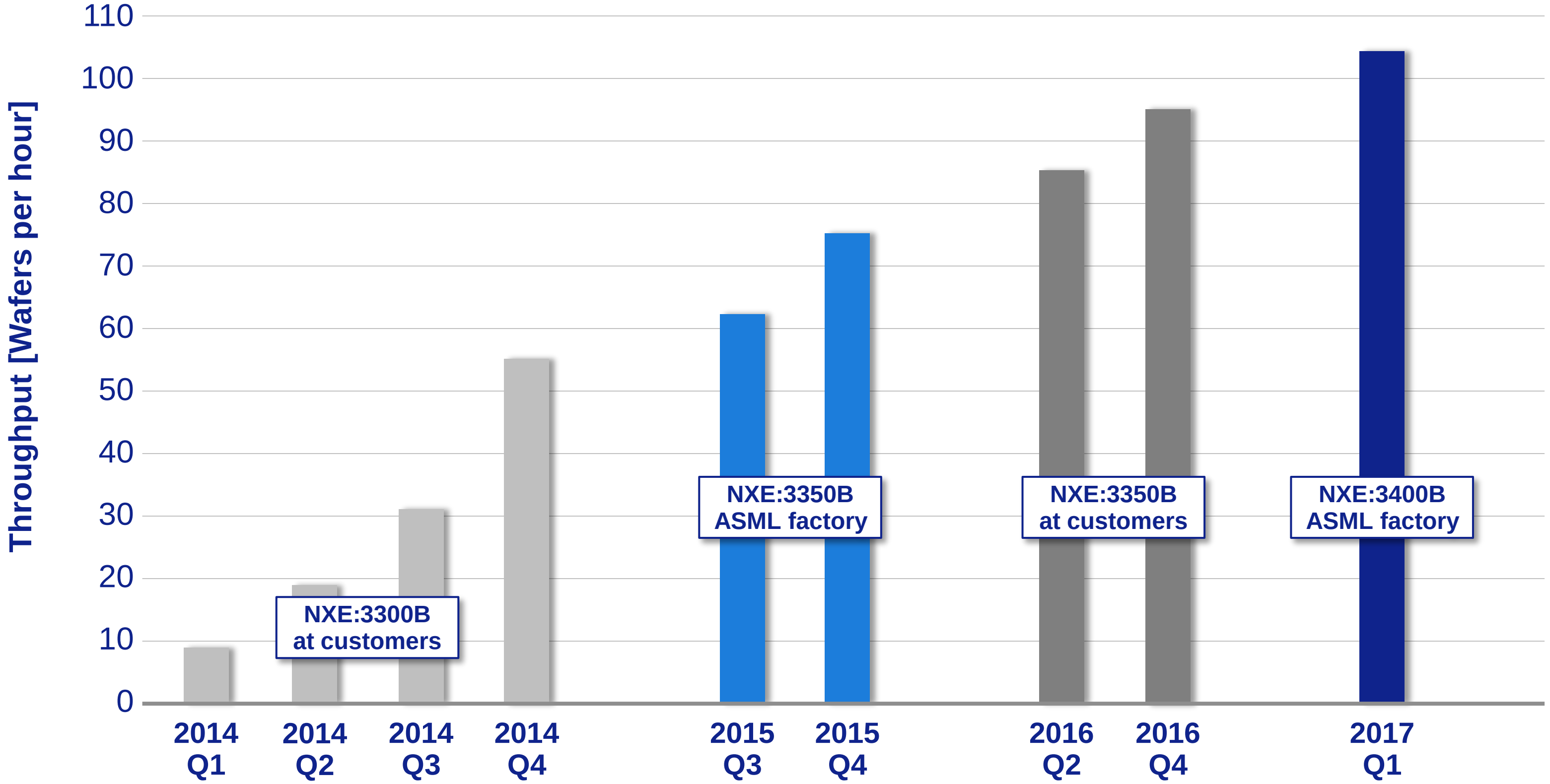
- **Restart capability**
- **Factory qualification**
- **Tin refill capability**
- **Enhanced particle elimination**



>70% reduction in average maintenance time

Feb’17: NXE scanner above **100** wafers per hour

NXE:3400B at 148W, **104 WPH**

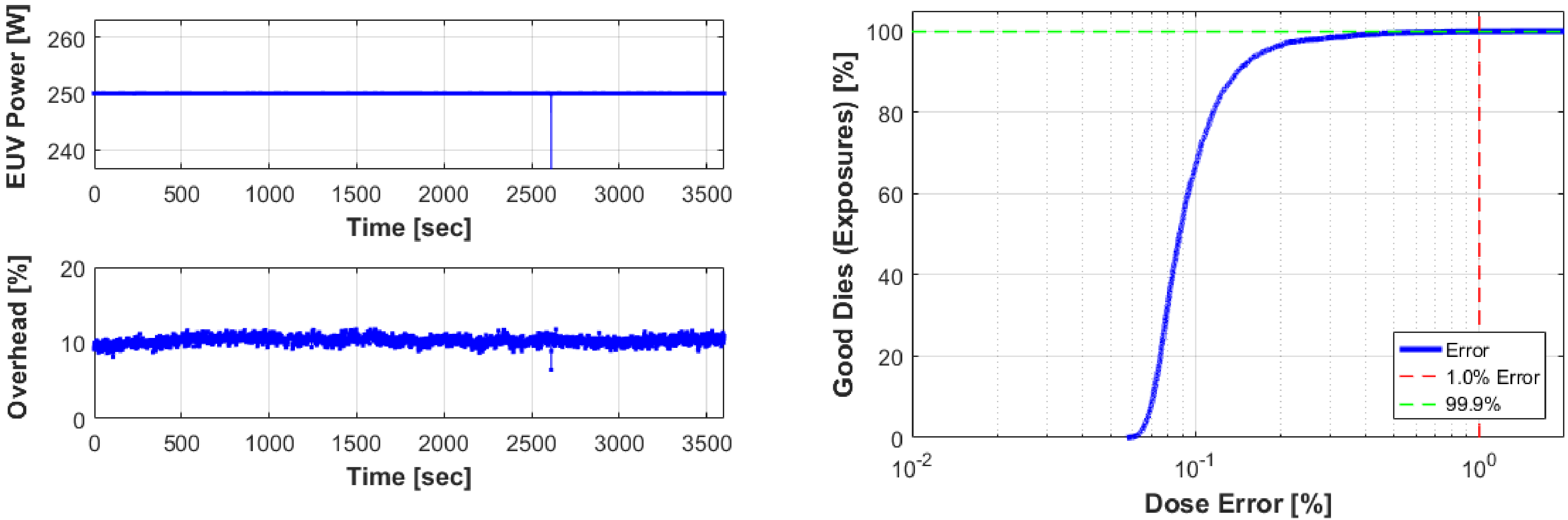


NXE:3400B ATP test: 26x33mm2, 96 fields, 20mJ/cm2

EUV Source Power Outlook

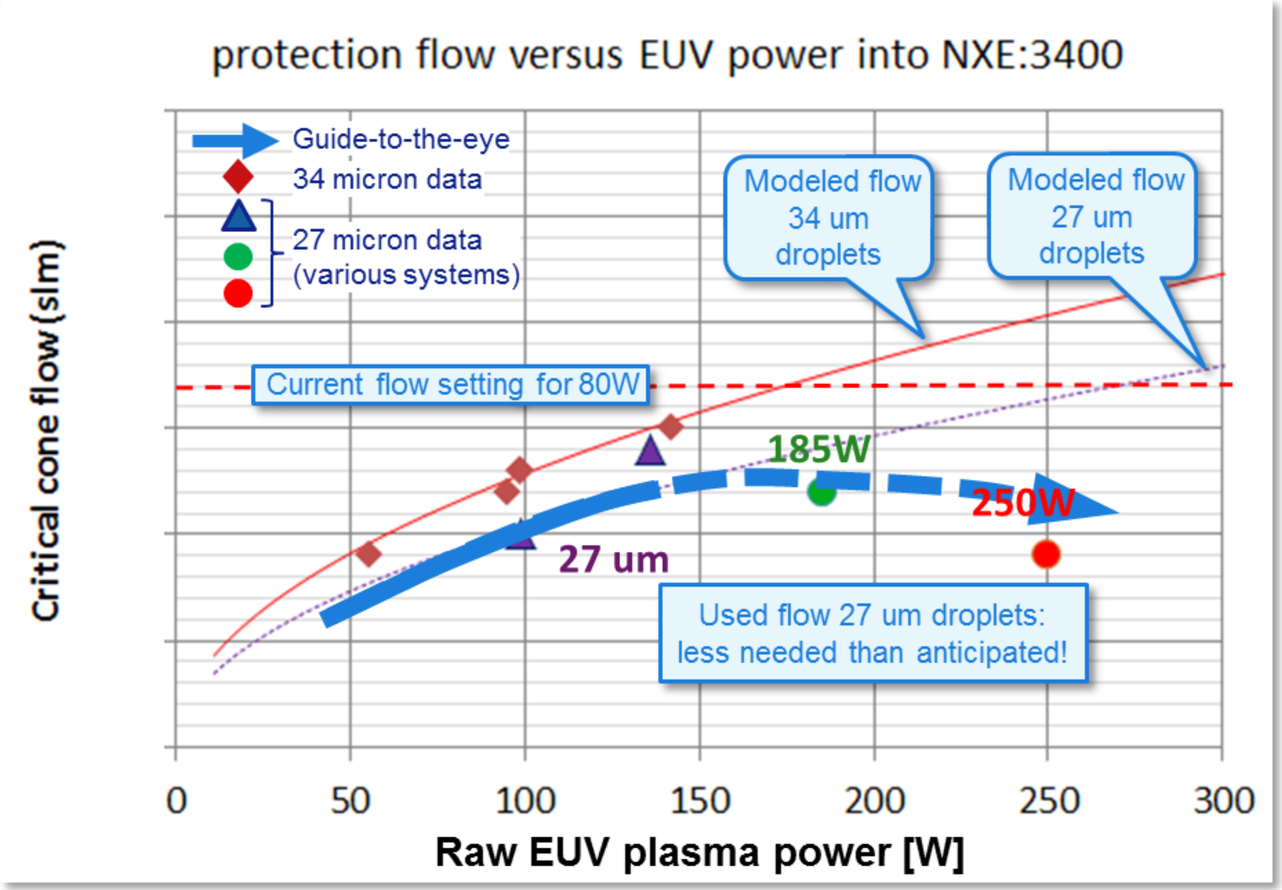
250W EUV power demonstration

with 99.90% fields meeting dose spec



Collector protection secured up to 250 W

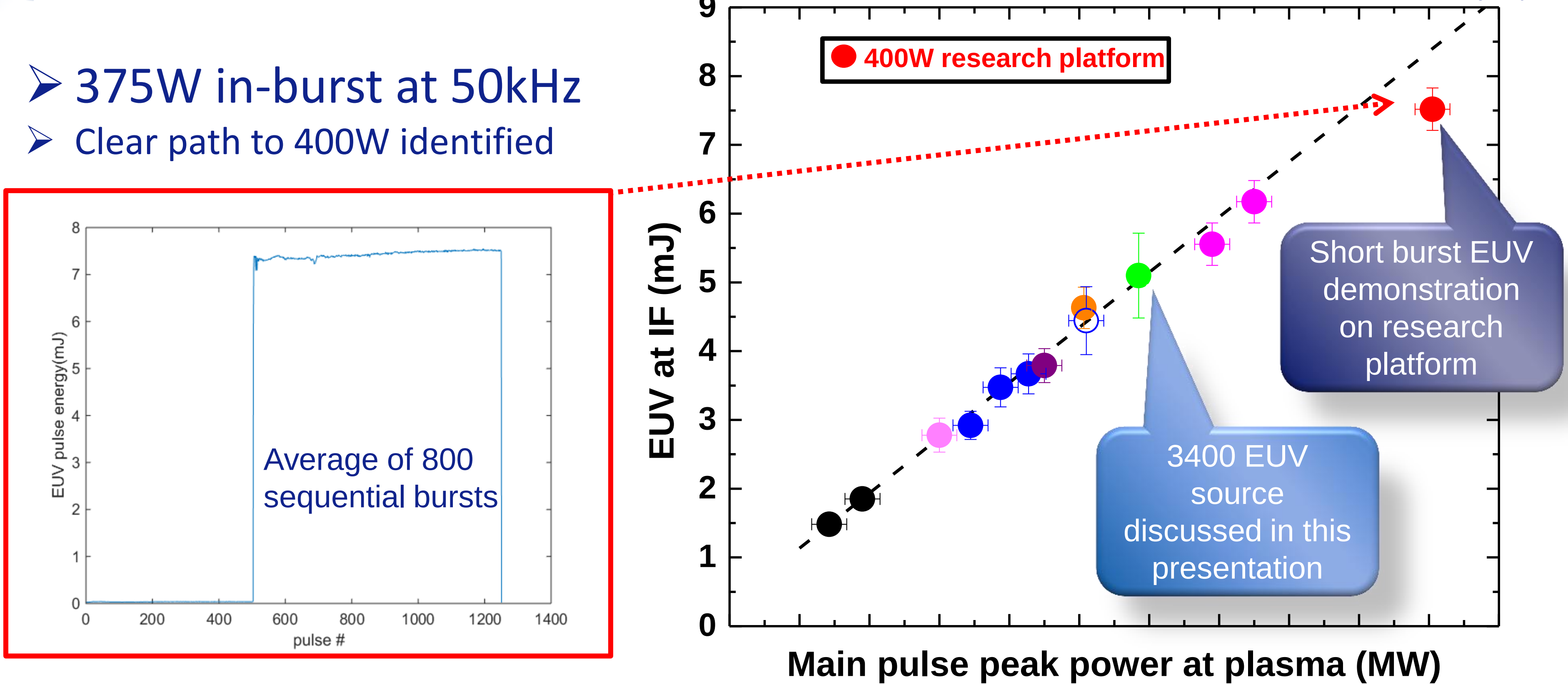
Collector protection demonstrated on research tool



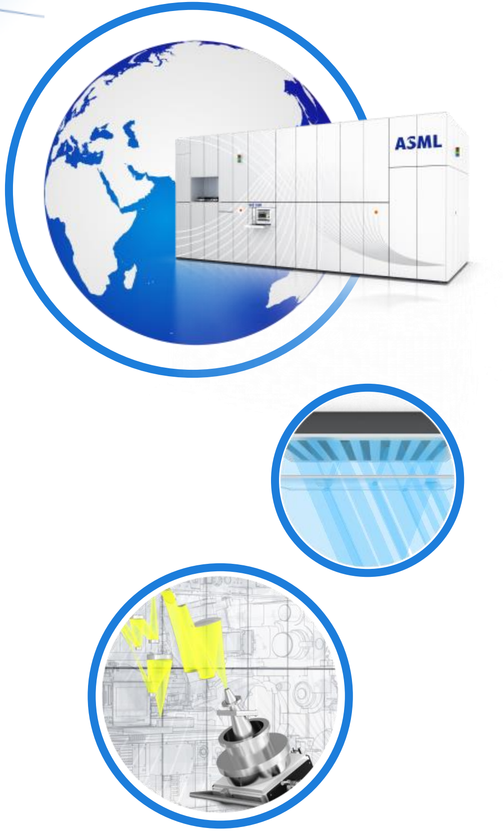
Research progress toward 400W EUV source

- Demonstrated EUV pulse energy of 7.5mJ

- 375W in-burst at 50kHz
- Clear path to 400W identified



Summary: EUV readiness for volume manufacturing



14 NXE:33X0B systems operational at customers

Significant progress in EUV power scaling for HVM
- Dose-controlled power of 250W
- EUV CE of 5.7%

CO_2 development supports EUV power scaling
- Clean (spatial and temporal) amplification of short CO_2 laser pulse
- High power seed system enables CO_2 laser power scaling

Droplet Generator with improved lifetime and reliability
- >700 hour average runtime in the field
- >3X reduction of maintenance time

Path towards 400W EUV demonstrated in research
- CE is up to 6 %
- In-burst EUV power is up to 375W

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